

Intel[®] Server Board SE7520JR2 Memory Test List

Revision 64.0
October 2008

Revision History

Date	Rev	Modifications
Aug/04	1.0	Initial Release
Sept/04	2.0	Added statement "The E7520 Chipset only supports BGA DRAM module Technology for DDR333". Added Legend* 256MB parts. Added Smart* 1GB part. Added Micron* 256MB and 1GB parts. (In shaded area)
Sep/04	3.0	Added Samsung*, Infineon*, TRS* and Dataram* 512MB parts. Added TRS*, Smart and Kingston* 1GB parts. (In shaded area)
Oct/04	4.0	Added Legend 256MB parts. Added TRS, Micron* and ATP* 512MB parts. Added Smart 1GB parts. Added Dataram 2GB parts. Correction made for Smart 2GB part from SR to DR. (In shaded area)
Oct/04	5.0	Added Samsung 256MB and 512MB parts. Added Infineon 256MB and 512MB parts. Added Micron 256MB and 1GB parts. Remove Micron 512MB part. (In shaded area)
Oct/04	6.0	Added Samsung and Infineon 256MB parts. Added Micron 256MB and 512MB parts. Correction made to Micron 512MB part, was listed as DDR333, now listed as DDR266. Added Smart, Dataram, Centon* and Viking* 1GB parts. Added TRS 512MB and 2GB parts. (In shaded area)
Oct/04	7.0	Added ATP 256MB part. Added Smart and Samsung 512MB parts. Added ATP, Smart, TRS, Corsair*, Dataram and Hynix*1GB parts. Added Wintec* 2GB parts. (In shaded area)
Nov/04	8.0	Corrected Infineon 512MB part number. Added Wintec, Smart, Legacy*, ATP, Kingston, Infineon and Hynix 512MB parts. Added Ventura*, Swissbit*, TRS, ATP, Wintec, Smart and Infineon 1GB parts. Added Ventura, Legacy and Smart 2GB parts. (In shaded area)
Nov/04	9.0	Added ATP 256MB parts. Added Swissbit, Smart and Wintec 1GB parts. Added Kingston 2GB parts. (In shaded area)
Dec/04	10.0	Added Corsair and Samsung 512MB parts. Added ATP and Legacy 1GB parts. Added Samsung 2GB part. (In shaded area)
Dec/04	11.0	Added Corsair 512MB and Smart 1GB and Dataram 2GB parts. (In shaded area)
Dec/04	12.0	Added Buffalo* 256MB and 512MB parts. Added Wintec, Hynix and Micron 512MB parts. Added Dataram and Samsung 1GB parts. Added Legacy and Micron 2GB parts. (In shaded area)
Dec/04	13.0	Added legacy 2GB parts. (In shaded area)
Jan/05	14.0	Added Legacy and Apacer 512MB parts. Added Legacy, Smart and Apacer 1GB parts. Added Viking, Smart and Samsung 2GB parts. (In shaded area)
Jan/05	15.0	Added Kingston and Micron 1GB parts. Added Dataram and Smart 2GB parts. (In shaded area)
Feb/05	16.0	Added Micron 256MB part. Added Infineon 512MB part. Added Legacy, Swissbit and Infineon 1GB parts. Added ATP 2GB parts. (In shaded area)
Feb/05	17.0	Added Samsung 256MB, 512MB, 1GB and 2GB parts. Added Smart and Netlist 1GB parts. Added Dataram 512MB parts. (In shaded area)
Mar/05	18.0	Added Ventura 512MB parts. Added Smart and Samsung 1GB parts. Added ATP 2GB parts. (In shaded area)
Mar/05	19.0	Added note on Lead free modules (these modules are now in bold text). Added Dane-elec and Apacer 512MB parts. Added Swissbit, Viking, ATP, Samsung and Infineon 1GB parts. Added Dataram, Smart, and ATP 2GB parts. (In shaded area)
Mar/05	20.0	Added Netlist Inc* 1GB Lead free part. (In shaded area)
Apr/05	21.0	Added Centon 512MB parts. Added Legend, Ventura, Centon, Dane-elec*, Hynix, Micron and Viking 1GB parts. Added ATP 2GB parts. (In shaded area)
Apr/05	22.0	Added Viking, Ventura, Simple, Samsung and Kingston 512MB parts. Added Simple, Samsung, Infineon and Ventura 1GB parts. Added Kingston and Smart 2GB parts. Added Micron 4GB part. (In shaded area)
May/05	23.0	Added Kingston and Samsung 512MB parts. Added Avant, Ventura, Netlist, and Apacer 1GB parts. Added Netlist* and Infineon 2GB parts. (In shaded area)
May/05	24.0	Added ATP 256MB parts. Added Avant 512MB parts. Added Viking, Kingston, Transcend*, and Dataram 1GB parts. Added Avant and Kingston 2GB parts.

Date	Rev	Modifications
Jun/05	25.0	Added TRS and ATP 512MB parts. Added Corsair, Wintec, Apacer and Simple* 1GB parts. Added Dataram and Smart 2GB parts. (In shaded area)
Jun/05	26.0	Added Legacy 512MB and 1GB parts. Added Avant* and Smart 2GB parts. Added Samsung 1GB, 2GB and 4GB parts. (In shaded area)
Jun/05	27.0	Added Apacer and Viking 512MB parts. Added Dataram, Kingston, Apacer and Viking 1GB parts. Added Smart and Apacer 2GB parts. Added ATP 4GB parts. (In shaded area)
Aug/05	28.0	Added Kingston and Apacer 512MB parts. Added Apacer, Wintec, Avant, Kingston and Samsung 1GB parts. Added TRS, Wintec, and Dataram 2GB parts. Added Infineon 512MB, 1G & 2G parts. (In shaded area)
Aug/05	29.0	Added Samsung 1GB part. Added Legacy and Samsung 2GB parts. Added Dataram 4GB parts. Added Viking 512MB parts. Added Legacy, Micron and Smart DDR2 1GB parts. Added Micron and Kingston DDR2 2GB parts. Added Wintec and Micron DDR2 512MB parts. (In shaded area)
Sept/05	30.0	Added Micron 512MB part. Added Dataram DDR2 512MB part. Added Kingston DDR2 1GB part. Added Samsung 1GB parts. Added Micron 2GB part. Added Samsung DDR2 2GB part. (In shaded area)
Oct/05	31.0	Added Samsung and Micron 512MB parts. Added Samsung 1GB part. Added Viking 2GB part. Added Wintec, Samsung and Dataram DDR2 1GB part. Added Smart DDR2 4GB part. (In shaded area)
Oct/05	32.0	Added Apacer, Nanya*, Legacy and Ventura DDR2 512MB parts. Added Hynix 1GB part. Added Corsair, Kingston and Legacy DDR2 1GB parts. Added ATP and Smart DDR2 2GB parts. (In shaded area)
Nov/05	33.0	Added Samsung 256MB parts. Added Kingston, Samsung and Hynix 512MB parts. Added Legend, Nanya, Legacy, Smart, Hynix, Samsung and Avant 1GB parts. Added Nanya, Hynix, Samsung and ATP 2GB parts. Added Smart, Infineon and Hynix 4GB parts. (In shaded area)
Nov/05	34.0	Updated two Micron 1GB parts with corrected DRAM part numbers. (in shaded area)
Dec/05	35.0	Added Kingston 2GB part. Added Kingston DDR2 2GB and 4GB parts. Added Legacy DDR2 2GB part. (In shaded area)
Jan/06	36.0	Corrected Samsung 2GB part that was listed as single ranked incorrectly. Added ATP and Apacer DDR2 512MB parts. Added Legacy DDR2 1GB part. Added Smart DDR2 256MB part. (In shaded area)
Jan/06	37.0	Samsung DDR1 256MB, 512MB, 1G & 2G parts. Hynix DDR1 1G part. Added Apacer, Kingston and Smart DDR2 1GB parts. Added Legacy, Legend & Samsung DDR2 2GB parts. Added Smart DDR2 512MB part. Added Hynix DDR2 512MB, 1G & 2G parts. (In shaded area)
Feb/06	38.0	Added SimpleTech and Dataram DDR2 1GB parts. Added Kingston DDR2 2GB part. Added Infineon DDR1 1G & 2G parts. Added Hynix DDR2 1G & 2G parts. (In shaded area)
Mar/06	39.0	Added Legend and Legacy 1GB parts. Added Legend, Buffalo and Dataram DDR2 512MB parts. Added Legend, ATP, MDT, Dataram and Kingston DDR2 1GB parts. (In shaded area)
Mar/06	40.0	Added Dataram 1GB and 2GB parts. Added Transcend DDR2 512MB and 1GB parts. Added Kingston DDR2 2GB and 4GB parts. Added Legacy DDR2 2GB part. Added Ventura DDR2 512MB (In shaded area)
May/06	41.0	Infineon name change to Qimonda effective May 1 st , 2006. Added ATP 1G part. Added Dataram 1G, 2G & 4G parts. Added TRS 512MB, 1G & 2G parts. (In shaded area)
June/06	42.0	Added Buffalo 512MB part. Added Dataram 4G part. Added Kingston 1G and 2G parts. Added MDT, Smart, and Transcend 1G parts. Added TRS 512MB and 1G parts. Added Wintec 1G parts. (In shaded area)
July/06	43.0	Added Kingston and TRS 512MB parts. Added Kingston, TRS, Netlist Inc., and Smart 1GB parts. Added Kingston 2GB part. (In shaded area)
Aug/06	44.0	Added Dane-Elec 1GB part. Added Kingston 2GB part. (In shaded area)
Aug/06	45.0	Added TRS and Super Talent Electronics 512MB parts. Added TRS 2GB part. (In shaded area)

Date	Rev	Modifications
Oct/06	46.0	Added Super Talent Electronics, TRS, SimpleTech, and Corsair 512MB parts. Added Super Talent Electronics, TRS, Kingston, and Avant Technology 1GB parts. Added Super Talent Electronics and Smart 2GB parts. Added Smart 4GB parts. (In shaded areas)
Nov/06	47.0	Added Kingston and Viking 512MB parts. Added Kingston, Viking, and Avant Technology 1GB parts. Added Kingston 2GB part. (In shaded areas)
Jan/07	48.0	Added Kingston 1GB part. Added Ventura, Smart, and Kingston 2GB parts. (In shaded area)
Jan/07	49.0	Added Micron 512MB and 1GB parts. Added Legacy 2GB part. Added Smart Modular Technologies 4GB part. (In shaded area)
Feb/07	50.0	Added Samsung 4GB part. (In shaded area)
Feb/07	51.0	Added TRS 1GB part. (In shaded area)
Feb/07	52.0	Added All Components 1GB part. Added Kingston 4GB part. Updated vendor contact information. (In shaded area)
Mar/07	53.0	Updated contact information. Added Kingston 512MB part. Added US Technology 1GB part. (In shaded area)
Apr/07	54.0	Added STEC Inc.* 2GB part. Added Dataram 4GB part. (In shaded area)
May/07	55.0	Added Kingston 1GB and 2GB parts. (In shaded area)
May/07	56.0	Additional memory parts added. (In shaded area)
Aug/07	57.0	Additional memory parts added. (In shaded area)
Nov/07	58.0	Additional memory parts added. (In shaded area)
Jan/08	59.0	Additional memory parts added. (In shaded area)
Mar/08	60.0	Additional memory parts added. (In shaded area)
June/08	61.0	Additional memory parts added. (In shaded area)
June/08	62.0	Additional memory parts added. (In shaded area)
July/08	63.0	Additional memory parts added. (In shaded area)
Oct 08	64.0	Additional memory parts added. (In shaded area)

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The Intel® Server Board SE7520JR2 may contain design defects or errors known as errata which may cause the product to deviate from published specifications. Current characterized errata are available on request.

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Please Note: DIMM devices with gold contacts should NOT be placed into DIMM sockets with tin-lead contacts or vice-versa. Mixing dissimilar metal contact types has been shown to result in unreliable memory operation. Intel recommends similar manufacturer and similar speeds in each Rank on the memory module. Mixing of dissimilar memory manufacturer and similar speeds in each Rank on the memory module is NOT recommended.

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1. Overview of Memory Testing

The following test processes are used to qualify Dual In-Line Memory Modules (DIMMs) for use with the Intel® Server Board SE7520JR2. Memory is a vital subsystem in a server. Intel requires that strict guidelines be met before a DIMM vendor is added to the Tested memory List. To be included on the list as a fully supported DIMM, the memory must undergo rigorous tests to ensure that the product will perform the intended server product functions. Memory qualification for Intel server, workstation, and RAID Controller products is performed both by Intel's Memory Validation Lab (MVL) and by an independent external test lab, Computer Memory Test Lab* CMTL).

The Tested Memory Lists for Intel's server board, workstation board, and RAID controller products categorize memory modules as advanced tested. The advanced testing process includes a standard paper qualification and then is followed by two levels of functional testing. DIMMs that have completed and passed Advanced Testing are considered to be compatible with the product on which they were tested, and with the test software and operating systems that was used during the test process.

1.1 Paper Qualification

A paper qualification is performed to verify that the specifications of a given DIMM meet Intel's memory specifications for a given product. Specification criteria reviewed include: critical timings, electrical characteristics, timing requirements, environmental requirements, and packaging requirements.

1.2 Functional Testing

After a given DIMM passes the standard paper qualification, functionality of the DIMM is then tested with the intended Intel product. Two levels of functional testing are performed; standard and advanced.

Standard functional testing requires that the given DIMM and Intel product combination operate with no failures for a period of no less than 24 hours for both minimum and maximum DIMM configurations. Testing is performed using a Microsoft* Windows* operating system and a custom test package. The test systems operate with standard voltage at room temperature.

Advanced functional testing requires that the given DIMM and Intel product combination operate with no failures for a period of no less than 24 hours for both minimum and maximum DIMM configurations. Testing is performed with multiple operating systems and various custom test packages. Each test configuration is tested with various voltage and temperature margin conditions.

1.3 Computer Memory Test Lab*

Computer Memory Test Lab, also known as CMTL*, is a leading memory test organization responsible for testing a broad range of memory products. A memory product, which receives a "PASS" after being tested by CMTL, means it functions correctly and consumers can use the product to perform the intended server functions. In order to pass these stringent standards, memory products must maintain the highest manufacturing procedures and pass an exacting battery of tests. Testing is performed with Intel supplied equipment and procedures defined by Intel's various functional testing levels.

CMTL Contact Info:

Office: (949) 716-8690
Fax: (949) 716-8691

Computer Memory Test Lab (CMTL)
24 Hammond Suite F
Irvine, CA 92618
<http://www.cmtlabs.com/>

2. Memory Subsystem

The Intel® Server Board SE7520JR2 is capable of supporting either DDR266/333 or DDR2-400 memory technologies depending on which baseboard SKU is being used.

NOTE: Industry naming conventions for equivalent memory technologies include the following:

- DDR266 = PC2100
- DDR333 = PC2700
- DDR2400 = PC23200

The following maximum memory capacities are supported based on the number of DIMM slots provided and maximum supported memory loads by the chipset:

24GB maximum capacity for DDR266
16GB maximum capacity for DDR333 and DDR2-400

The minimum memory supported with the system running in single channel memory mode is:

256MB for DDR256, DDR333 and DDR2-400.

Supported DIMM capacities are as follows:

DDR266 Memory DIMM sizes include: 256MB, 512MB, 1GB, 2GB, and 4GB.
DDR333 Memory DIMM sizes include: 256MB, 512MB, 1GB, 2GB, and 4GB.
DDR2-400 Memory DIMM sizes include: 256MB, 512MB, 1GB, 2GB, and 4GB.

2.1 Memory Population

The Intel® Server Board SE7520JR2 has six DIMM slots, or three DIMM banks. Both DIMMs in a bank should be identical (same manufacturer, CAS latency, number of rows, columns and devices, timing parameters etc.). Although DIMMs within each bank must be identical, the BIOS supports various DIMM sizes and configurations allowing the banks of memory to be different. Memory sizing and configuration is guaranteed only for qualified DIMMs approved by Intel.

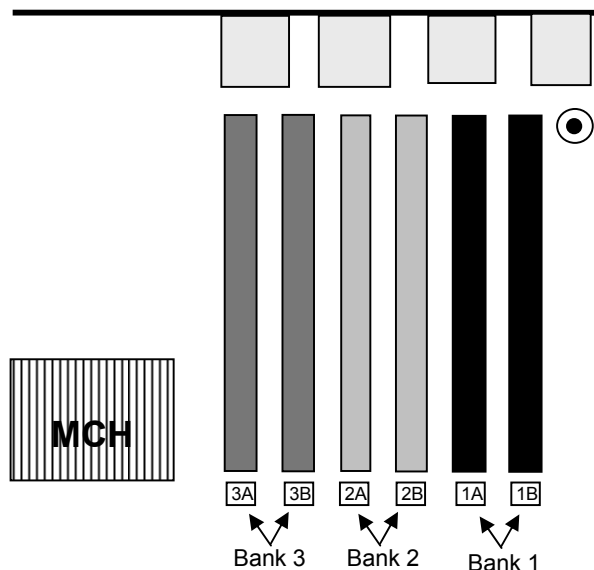


Figure 1. Identifying Banks of Memory

Mixing of DDR266 and DDR333 DIMMs is supported between banks of memory. However, when mixing DIMM types, DDR333 will run at DDR266 speeds.

The memory controller is capable of supporting up to 4 loads per channel for DDR333 and DDR2-400. Memory technologies are classified as being either single rank or dual rank depending on the number of DRAM devices that are used on any one DIMM. A single rank DIMM is a single load device, i.e.) Single Rank = 1 Load. Dual rank DIMMs are dual load devices, i.e.) Dual Rank = 2 loads.

DDR266 and DDR333 DIMM population rules are as follows:

- (1) DIMM banks must be populated in order starting with the slots furthest from MCH
- (2) Single rank DIMMs must be populated before dual rank DIMMs
- (3) A maximum of four DIMMs can be populated when all four DIMMs are dual rank DDR333 DIMMs.

DDR2-400 DIMM population rules are as follows:

- (1) DIMMs banks must be populated in order starting with the slots furthest from MCH
- (2) Dual rank DIMMs are populated before single rank DIMMs
- (3) A maximum of four DIMMs can be populated when all four DIMMs are dual rank DDR2-400 DIMMs

The following tables show the supported memory configurations:

- s/r = single rank
- d/r = dual rank
- E = Empty

Table 1: Supported DDR266 DIMM Populations

MCH	Bank 3 – DIMMs 3A, 3B	Bank 2 – DIMMs 2A, 2B	Bank 1 – DIMMs 1A, 1B
	S/R	S/R	S/R
	E	S/R	S/R
	E	E	S/R
	D/R	D/R	D/R
	E	D/R	D/R
	E	E	D/R
	D/R	S/R	S/R
	D/R	D/R	S/R
	E	D/R	S/R

Table 2: Supported DDR333 DIMM Populations

MCH	Bank 3 – DIMMs 3A, 3B	Bank 2 – DIMMs 2A, 2B	Bank 1 – DIMMs 1A, 1B
	S/R	S/R	S/R
	E	S/R	S/R
	E	E	S/R
	E	D/R	D/R
	E	E	D/R
	D/R	S/R	S/R
	E	D/R	S/R

Table 3: Supported DDR2-400 DIMM Populations

MCH	Bank 3 – DIMMs 3A, 3B	Bank 2 – DIMMs 2A, 2B	Bank 1 – DIMMs 1A, 1B
	S/R	S/R	S/R
	E	S/R	S/R
	E	E	S/R
	E	D/R	D/R
	E	E	D/R
	E	S/R	D/R
	S/R	S/R	D/R

Note: On the **Server Board SE7520JR2**, when using all dual rank DDR333 or DDR2-400 DIMMs, a total of four DIMMs can be populated. Configuring more than four dual rank DDR333 or DDR2-400 DIMMs will result in the BIOS generating a memory configuration error.

2.2 Identifying “Single Rank” or “Double Ranked” DIMMs

- **x8SR** = x8 *Single-Ranked modules* - have 5 DRAMs on the front and 4 DRAMs on the back with empty spots in between the DRAMs.
- **x8DR** = x8 *Double-Ranked modules* - have 9 DRAMs on each side for a total of 18 (no empty slots)
- **x4SR** = x4 *Single-Ranked modules* - have 9 DRAMs on each side for a total of 18 – and look similar to x8 Double-Ranked
- **x4DR** = x4 *Double-Ranked modules* - have 18 (stacked) DRAMs on each side for a total of 36

The following tables list the current supported memory types:

DDR266 Registered SDRAM Module Matrix						
DIMM Capacity	DIMM Organization	SDRAM Density	SDRAM Organization	# SDRAM Devices/rows/Ranks	# Address bits rows/Ranks/column	Ranked
256MB	32M x 72	128Mbit	32M x 4	18/1/4	12/2/11	Single Ranked
256MB	32M x 72	128Mbit	16M x 8	18/2/4	12/2/10	Double Ranked
256MB	32M x 72	256Mbit	32M x 8	9/1/4	13/2/10	Single Ranked
512MB	64M x 72	256Mbit	64M x 4	18/1/4	13/2/11	Single Ranked
512MB	64M x 72	256Mbit	32M x 8	18/2/4	13/2/10	Double Ranked
512MB	64M x 72	512Mbit	64M x 8	9/1/4	13/2/11	Single Ranked
1GB	128M x 72	256Mbit	64M x 4	36/2/4	13/2/11	Double Ranked
1GB	128M x 72	512Mbit	64M x 8	18/2/4	13/2/11	Double Ranked
1GB	128M x 72	512Mbit	128M x 4	18/1/4	13/2/12	Single Ranked
2GB	256M x 72	512Mbit	128M x 4	36/2/4	13/2/12	Double Ranked
4GB	TBD	TBD	TBD	TBD	TBD	TBD
DDR333 Registered SDRAM Module Matrix						
Note: The E7520 Chipset only supports BGA DRAM module Technology for DDR333						
DIMM Capacity	DIMM Organization	SDRAM Density	SDRAM Organization	# SDRAM Devices/rows/Ranks	# Address bits rows/Ranks/column	Ranked
256MB	32M x 72	128Mbit	32M x 4	18/1/4	12/2/11	Double Ranked
256MB	32M x 72	128Mbit	16M x 8	18/2/4	12/2/10	Double Ranked
256MB	32M x 72	256Mbit	32M x 8	9/1/4	13/2/10	Single Ranked
512MB	64M x 72	256Mbit	64M x 4	18/1/4	13/2/11	Single Ranked
512MB	64M x 72	256Mbit	32M x 8	18/2/4	13/2/10	Double Ranked
512MB	64M x 72	512Mbit	64M x 8	9/1/4	13/2/11	Single Ranked
1GB	128M x 72	512Mbit	128M x 4	18/1/4	13/2/12	Single Ranked
1GB	128M x 72	512Mbit	64M x 8	18/2/4	13/2/11	Double Ranked
1GB	128M x 72	1Gbit	128M x 4	9/1/4	14/2/11	Single Ranked
2GB	256M x 72	1Gbit	128M x 4	18/1/4	14/2/12	Single Ranked
2GB	256M x 72	1Gbit	128M x 8	18/2/4	14/2/11	Double Ranked
4GB	TBD	TBD	TBD	TBD	TBD	TBD

DDR2-400 Registered SDRAM Module Matrix						
DIMM Capacity	DIMM Organization	SDRAM Density	SDRAM Organization	# SDRAM Devices/rows/Ranks	# Address bits rows/Ranks/column	Ranked
256MB	32M x 72	256Mbit	32M x 8	9/1/4	13/2/10	Single Ranked
512MB	64M x 72	256Mbit	64M x 4	18/1/4	13/2/11	Single Ranked
512MB	64M x 72	256Mbit	32M x 8	18/2/4	13/2/10	Double Ranked
512MB	64M x 72	512Mbit	64M x 8	9/1/4	14/2/10	Single Ranked
1GB	128M x 72	512Mbit	128M x 4	18/1/4	14/2/11	Single Ranked
1GB	128M x 72	512Mbit	64M x 8	18/2/4	14/2/10	Double Ranked
1GB	128M x 72	1Gbit	128M x 8	9/1/8	14/3/10	Single Ranked
2GB	256M x 72	1Gbit	256M x 4	18/1/8	14/3/11	Single Ranked
2GB	256M x 72	1Gbit	128M x 8	18/2/8	14/3/10	Double Ranked
2GB	256M x 72	2Gbit	256M x 8	9/1/8	15/3/10	Single Ranked
4GB	512M x 72	2Gbit	256M x 8	18/2/8	15/3/10	Double Ranked
4GB	512M x 72	2Gbit	512M x 4	18/1/8	15/3/11	Single Ranked
4GB	512M x 72	4Gbit	512M x 8	9/1/8	TBD	Single Ranked

3. Tested Memory

The following tables list DIMM devices tested to be compatible with the Intel® Server Board SE7520JR2. The list of tested memory is periodically updated as qualified memory is added during the production life of the Intel product.

Intel strongly recommends the use of ECC memory in all server products.

Memory modules not listed in the following tables have not been tested for compatibility and their use with the Intel® Server Board SE7520JR2 may result in unpredictable operation and data loss.

Caution: Third party memory vendors may use the same module part number with different DRAM vendors and die revisions. To insure proper system operation, verify that each DRAM vendor and die revision has been separately tested and qualified. Please notify CMTL if there is a discrepancy. This list is subject to change without notice.

Note: This list is not intended to be all-inclusive. It is provided as a convenience to Intel's general customer base, but Intel does not make any representations or warranties whatsoever regarding the quality, reliability, functionality, or compatibility of these memory modules.

Intel® Server Board SE7520JR2
Registered ECC, DDR-266 DIMM Modules
256MB Size (32M x 72)

Manufacturer	Part Number	DRAM Part Number	DRAM Vendor	PCB Part Number	Lead Free	DRAM Organization	Rank	Date
+Legend*	L6472YC5-RU1HDC5B	HY5DU56822BT-J rev B	Hyundai	DRR1U0818-A rev 1		(32Mx8)*18	x8DB	8/26/04
+Legend	L3272YC5-RU1HDC5B	HY5DU56822BT-J rev B	Hyundai	DRR1U0818-A rev 1		(32Mx8)*18	x8DB	9/20/04
Micron*	MT9VDDT3272G-265G3	MT46V32M8-6T G	Micron			(32Mx8)*9	x8SR	1/20/05

Registered ECC, DDR-333 DIMM Modules
256MB Size (32M x 72)

Manufacturer	Part Number	DRAM Part Number	DRAM Vendor	PCB Part Number	Lead Free	DRAM Organization	Rank	Date
Micron	MT9VDDF3272G-335G3	MT46V32M8FG-6	Micron			(32Mx8)*9	x8SR	8/31/04
Samsung*	M312L3223EG0-CB3	K4H560838E-GCB3	Samsung			(32Mx8)*9	x8SR	10/4/04
Qimonda	HYS72D32300GBR-6-C	HYB25D256800CC-6	Qimonda			(32Mx8)*9	x8SR	10/4/04
Micron	MT9VDDF3272G-335C1	MT46V32M8FG-6	Micron			(32Mx8)*9	x8SR	10/4/04
+ATP Electronics*	AB32L72V8BFB3S	K4H560838E-GCB3 rev E	Samsung	SB184V08L1		(32Mx8)*9	x8SR	10/13/04
Samsung	M312L3223EZ0-CB3	K4H560838E-ZCB3	Samsung		Yes	(32Mx8)*9	x8SR	2/24/05
Samsung	M312L3223EG3-CB3	K4H560838E-GCB3	Samsung			(32Mx8)*9	x8SR	11/15/05

Registered ECC, DDR2-400 DIMM Modules
256MB Size (32M x 72)

Manufacturer	Part Number	DRAM Part Number	DRAM Vendor	PCB Part Number	Lead Free	DRAM Organization	Rank	Date
Samsung	M393T3253FG0-CCC Date Code: 0521	K4T56083QF-GCCC	Samsung			(32Mx8)*9	x8SR	9/22/04
Micron	MT9HTF3272Y-40EB2	MT47H32M8BP-37E	Micron		Yes	(32Mx8)*9	x8SR	9/22/04
Qimonda	HYS72T32000HR-5-A	HYB18T256800AF5-A	Qimonda		Yes	(32Mx8)*9	x8SR	9/22/04
+ATP Electronics	AH32K72N8BQC4M	MT47H32M8BP(FP)-37E rev	Micron	SH240N08K1		(32Mx8)*9	x8SR	11/16/04
+Buffalo*	D2R400A-ES256MBJ	MT47H32M8BP(FP)-5E rev B	Micron	2DRA18F-BA		(32Mx8)*9	x8SR	12/7/04
Samsung	M393T3253FZ0-CCC Date Code: 0521	K4T56083QF-ZCCC	Samsung		Yes	(32Mx8)*9	x8SR	2/24/05
+ATP Electronics	AH32K72N8BQC4S	K4T56083QF-GCD5 rev F	Samsung	SH240N08K1		(32Mx8)*9	x8SR	5/4/05
Samsung	M393T3253FG3-CCC	K4T56083QF-GCCC	Samsung			(32Mx8)*9	x8SR	11/4/05
Samsung	M393T3253FZ3-CCC	K4T56083QF-ZCCC	Samsung		Yes	(32Mx8)*9	x8SR	11/4/05
+Smart Modular Technologies	SB327RDR23283-5-I	HYB18T256800AF5 rev A	Qimonda	0408 (240-11-4)	Yes	(32Mx8)*9	x8SR	12/8/05

(+) This vendor is part of the CMTL Certification program. This means this part has/will be tested across all compatible Intel Server Boards. For further information contact CMTL @ <http://cmtlabs.com/>

Caution: Some modules on this list may contain "stacked" DRAM parts. These parts may have thermal & physical limitations in some chassis configurations. It is advised to verify that your chassis configuration will support "stacked" parts before purchase.

Intel® Server Board SE7520JR2
Registered, ECC, DDR-266 DIMM Modules
512 MB Sizes (64Mx72)

Manufacturer	Part Number	DRAM Part Number	DRAM Vendor	PCB Part Number	Lead Free	DRAM Organization	Rank	Date
+TRS*	TRS21152	HYB25D256800BT-7 rev B	Qimonda	M0529LA1 rev 1		(32Mx8)*18	DR	9/3/04
+TRS	TRS21151	HYB25D256400BT-7 rev B	Qimonda	M0530LA1 rev 1		(64Mx4)*18	SR	9/13/04
Micron	MT18VDDF6472G-335C1	MT46V64M4-75 G	Micron			(32Mx8)*18	DR	9/20/04
+TRS	TRS21171	HYB25D256400BC-7 rev B	Qimonda	M0533LA1 rev 1		(64Mx4)*18	SR	10/4/04
Corsair*	CM72SD512RPL-2100/M	MT46V32M8TG(P)-75 rev G	Micron	50-00123 rev A		(32Mx8)*18	DR	11/24/04
Corsair	CM72SD512RPL-2100/S	K4H560838F-TCCC rev F	Samsung	50-00131 rev A		(32Mx8)*18	DR	11/29/04
Hynix*	HYMD264G726D4 M-H AA	HY5DU56422DT-H	Hynix			(64Mx4)*18	SR	12/16/04
+Viking*	VI4CR647228DTH L5	MT46V32M8TG(P)-6T rev G	Micron	0000985A		(32Mx8)*18	DR	4/1/05
Samsung	M312L6420ETS-CB0	K4H560438E-TCB0	Samsung		Yes	(64Mx4)*18	SR	4/13/05
Samsung	M312L6420EUS-CB0	K4H560438E-UCB0	Samsung		Yes	(64Mx4)*18	SR	4/13/05
+TRS	TRS21202	HYB25D256400CE-7 rev C	Qimonda	M0530LA1 rev 1		(64Mx4)*18	SR	6/2/05
Micron	MT18VDDT6472G-265G3	MT46V64M4-75 G	Micron			(32Mx8)*18	DR	9/20/04

Registered, ECC, DDR-333 DIMM Modules
512 MB Sizes (64Mx72)

Manufacturer	Part Number	DRAM Part Number	DRAM Vendor	PCB Part Number	Lead Free	DRAM Organization	Rank	Date
Micron	MT18VDDF6472G-335G3	4AGII D9BJR	Micron			(64Mx8)*9	SR	7/20/04
Qimonda	HYS72D64300GB R-6-C	HYB25D256400CC-6	Qimonda			(64Mx4)*18	SR	7/20/04
Qimonda	HYS72D64320GB R-6-B	HYB25D256800BC-6	Qimonda			(32Mx8)*18	DR	8/4/04
Qimonda	HYS72D64300GB R-6-B	HYB25D256400BC-6	Qimonda			(64Mx4)*18	SR	9/3/04
Samsung	M312L6420EG0-CB3	K4H560438E-GCB3	Samsung			(64Mx4)*18	SR	9/7/04
+Dataram*	DTM63676D	HYB25D256400CC-6 rev C	Qimonda	40018A rev A		(64Mx4)*18	SR	9/8/04
+ATP Electronics	AB64L72L4BFB3S	K4H560438E-GCB3 rev E	Samsung	SB184L04L1		(64Mx4)*18	SR	9/27/04
+ATP Electronics	AB64L72L4BFB3C	HYB25D256400BC-5 rev B	Qimonda	SB184L04L1		(64Mx4)*18	SR	9/23/04
Micron	MT18VDDF6472G-335C1	MT46V64M4FB-6	Micron			(32Mx8)*18	DR	9/20/04
+Smart Modular Technologies*	SM6472RDDR6H1 BGBC	HYB25D256400CC-6 rev C	Qimonda	184-22-2		(64Mx4)*18	SR	10/15/04

**Registered, ECC, DDR-333 DIMM Modules
512 MB Sizes (64Mx72)**

Manufacturer	Part Number	DRAM Part Number	DRAM Vendor	PCB Part Number	Lead Free	DRAM Organization	Rank	Date
+Wintec Industries*	3C944646-L	HYB25D256400CC-5 rev C	Qimonda	DR1G472B		(64Mx4)*18	SR	11/9/04
Qimonda	HYS72D64320GB R-6-C	HYB25D256800CC-6	Qimonda			(32Mx8)*18	DR	11/4/04
Hynix*	HYMD564G726BF 8N-J AA	HY5DU12822BF-J	Hynix			(64Mx8)*9	SR	11/15/04
+Legacy Electronics Inc.*	88S6JDGR-1NDG	HYB25D256400BC6 rev B	Qimonda	LE36DDF1844 RC rev B		(64Mx4)*18	SR	12/22/04
Samsung	M312L6420EZ0-CB3	K4H560438E-ZCB3	Samsung		Yes	(64Mx4)*18	SR	2/24/05
+Ventura Technology Group*	D52YCK44SV	K4H560438E-GCB3 rev E	Samsung	DR1G472B		(64Mx4)*18	SR	2/15/05
+Dane-Elec*	DLD333R072645H	MT46V64M4FG-5B rev G	Micron	DR1G472B		(64Mx4)*18	SR	3/10/05
+Centon Electronics*	TOP-003	K4H560438E-GCB3 rev E	Samsung	DR1G472B		(64Mx4)*18	SR	3/24/05
SimpleTech*	ST72E4K64ML-C06E	HYB25D256400CC-6 rev C	Qimonda	01269 rev A		(64Mx4)*18	SR	3/29/05
+Kingston*	KVR333S4R25/51 2I	HYB25D256400CC-6 rev C	Qimonda	2025161-001.B00		(64Mx4)*18	SR	4/12/05
+Ventura Technology Group	D52YCK44MV	MT46V64M4FG-6 rev G	Micron	DR1G472B		(64Mx4)*18	SR	4/5/05
+Avant Technology*	AVM7264R38C533 3K6-MTG	MT46V64M4FG-5B rev G	Micron	RCE0020-01 rev 1		(64Mx4)*18	SR	5/3/05
+Kingston	KVR333S4R25/51 2I	K4H560438E-GCB3 rev E	Samsung	2025161-001.B00 na		(64Mx4)*18	SR	7/22/05
+Viking	VI4CR647224DBK L1	HYB25D256400CC-6 rev C	Qimonda	0000999B rev B		(64Mx4)*18	SR	08/01/05
Micron	MT9VDDF6472G-335D3	MT46V64M8FG	Micron			(64Mx8)*9	SR	9/26/05
Samsung	M312L6523CZ0-CB3	K4H510838C-ZCB3	Samsung		Yes	(64Mx8)*9	SR	9/28/05
Hynix	HYMD564G726CF P8N-J	HY5DU12822CFP-J	Hynix			(64Mx8)*9	SR	10/24/05
Samsung	M312L6420EZ3-CB3	K4H560438E-ZCB3	Samsung			(64Mx4)*18	SR	11/15/05
Samsung	M312L6420EG3-CB3	M312L6420EG3-CB3	Samsung		Yes	(64Mx8)*9	SR	11/15/05
Samsung	M393T6450FG0-CCC Date Code: 0521	K4T56043QF-GCCC	Samsung			(64Mx4)*18	SR	9/22/04
Qimonda	HYS72T64000HR-5-A	HYB18T512800AF	Qimonda		Yes	(64Mx8)*9	SR	9/22/04
Qimonda	HYS72T64020HR-5-A	HYB18T256800AF5-A	Qimonda		Yes			9/22/04
+Smart Modular Technologies	SM647RDR26483-5-I	HYB18T512800AF(AC)5 rev A	Qimonda	240-11-4 rev C		(64Mx8)*9	SR	10/21/04
Samsung	M393T6553BG0-CCC	K4T51083QB-GCCC	Samsung			(64Mx8)*9	SR	10/28/04

**Registered, ECC, DDR-333 DIMM Modules
512 MB Sizes (64Mx72)**

Manufacturer	Part Number	DRAM Part Number	DRAM Vendor	PCB Part Number	Lead Free	DRAM Organization	Rank	Date
TRS	TRS21220	HYB25D256400BC-6 rev B	Qimonda	M0545LA1 rev 1	Yes			04/20/06
TRS	TRS21180	HYB25D256400CC-6 rev C	Qimonda	M0545LA1 rev 1		(64Mx4)*18	SR	05/02/06
Kingston	KVR333S4R25/51 2I	HYB25D256400CF-5 rev C	Qimonda	2025161- 001.B00 na	Yes	(64Mx4)*18	SR	3/21/07
Smart Modular Technologies	SG6472RDDR6H8 BGSD	K4H510838D-ZCCC rev D	Samsung	PG51G184N EBZBGIF rev A	Yes	(64Mx8)*9	SR	9/28/07

**Registered, ECC, DDR2-400 DIMM Modules
512 MB Sizes (64Mx72)**

Manufacturer	Part Number	DRAM Part Number	DRAM Vendor	PCB Part Number	Lead Free	DRAM Organization	Rank	Date
+Smart Modular Technologies	SM647RDR264835I A	HYB18T512800AC5 rev A	Qimonda	P54G240NE BUB1RA rev A		(64Mx8)*9	SR	11/4/04
+Legacy Electronics Inc.	S506472J20A-50A	HYB18T256400AF5 rev A	Qimonda	LE18DD2F24 04RRH rev 1		(64Mx4)*18	SR	11/11/04
+ATP Electronics	AH64K72M4BQC4S	K4T56043QF-GCCC rev F	Samsung	SH240M04K 1		(64Mx4)*18	SR	10/28/04
Kingston	KVR400D2R3/512	HYB18T512800AF5 rev A	Qimonda	2025263- 001.A00		(64Mx8)*9	SR	10/28/04
Samsung	M393T6453FG0- CCC Date Code: 0521	K4T56083QF-GCCC	Samsung			(32Mx8)*18	DR	11/29/04
+Wintec Industries	39C921284B-L	K4T51083QB-GCD5 rev B	Samsung	D2R872		(64Mx8)*9	SR	12/9/04
+Wintec Industries	39C921284B-GL	K4T51083QB-ZCD5 rev B	Samsung	D2R872 na		(64Mx8)*9	SR	07/29/05
Micron	MT9HTF6472Y- 40EB2	MT47H64M8CB-5E	Micron		Yes	(64Mx8)*9	SR	8/15/05
+Dataram	DTM63312A	HYB18T512800AF5 rev A	Qimonda	40042A rev A		(64Mx8)*9	SR	9/12/05
+Buffalo	D2R400A-E512MBJ	MT47H32M8BP(FP)- 5E rev B	Micron	2DRB28F-BA		(32Mx8)*18	DR	12/6/04
Micron	MT18HTF6472Y- 40EB2		Micron		Yes			12/13/04
Hynix	HYMP564R728-E3 AA	HY5PS12821-F-E3	Hynix			(64Mx8)*9	SR	12/13/04
+Apacer*	75.963A1.565	K4T51083QB-GCCC rev B	Samsung	48.16188.011 rev 1		(64Mx8)*9	SR	12/20/04
Qimonda	HYS72T64001HR- 5-A	HYB18T256400AF5-A	Qimonda		Yes	(64Mx4)*18	SR	1/31/05
+Dataram	DTM63311C	K4T56043QF-GCCC rev F	Samsung	40011A rev A		(64Mx4)*18	SR	1/31/05
Samsung	M393T6553BZ0- CCC	K4T51083QB-ZCCC	Samsung		Yes	(64Mx8)*9	SR	2/24/05
Samsung	M393T6453FZ0- CCC Date Code: 0521	K4T56083QF-ZCCC	Samsung		Yes	(32Mx8)*18	DR	2/24/05

**Registered, ECC, DDR2-400 DIMM Modules
512 MB Sizes (64Mx72)**

Manufacturer	Part Number	DRAM Part Number	DRAM Vendor	PCB Part Number	Lead Free	DRAM Organization	Rank	Date
Samsung	M393T6450FZ0-CCC Date Code: 0521	K4T56043QF-ZCCC	Samsung		Yes	(64Mx4)*18	SR	2/24/05
+Apacer	75.963A1.573	K4T51083QB-ZCCC rev B	Samsung	48.16188.0 11 rev 1		(64Mx4)*18	SR	3/1/05
+Kingston	KVR400D2S8R3/512 I	HYB18T512800AF37 rev A	Qimonda	2025263- 001.A00 rev A		(64Mx8)*9	SR	4/27/05
Samsung	M393T6553CZ0-CCC	K4T51083QC-ZCCC	Samsung		Yes	(64Mx8)*9	SR	5/2/05
+ATP Electronics	AH64K72N8BHC4S	K4T51083QB-GCCC rev B	Samsung	SH240N08 K1		(64Mx8)*9	SR	5/12/05
+Legacy Electronics Inc.	L506472K20A-50A	G64Mx8DDR2	Legacy	LE9DD2F2 408RRA rev A		(64Mx8)*9	SR	6/7/05
+Apacer	76.92220.B07	K4T51083QB-ZCD5 rev B	Samsung	48.16188.0 11 rev 1		(64Mx8)*9	SR	6/22/05
+Apacer	76.92220.B12	HYB18T512800AF5 rev A	Qimonda	48.16188.0 11 rev 1		(64Mx8)*9	SR	6/23/05
+Viking	VR5ER647218EBPL 1	MT47H64M8CB-37E rev B	Micron	0000992A rev A		(64Mx8)*9	SR	6/20/05
+Apacer	76.92220.B03	K4T51083QB-ZCCC rev B	Samsung	48.16188.0 11 rev 1		(64Mx8)*9	SR	6/30/05
+Apacer	76.92220.B13	EDE5108AESK-5C-E rev E	Elpida	48.16188.0 11 rev 1		(64Mx8)*9	SR	7/11/05
+Kingston	KVR400D2S8R3/512 I	HYB18T512800AF37 rev A	Qimonda	2025263- 001.C00 na		(64Mx8)*9	SR	7/5/05
Qimonda	HYS72T64000HR-5- A	HYB18T512800AC5	~ Qimonda (Infineon)		Yes	(64Mx8)*9	SR	7/8/05
+Apacer	75.963A1.G01	EDE5108AGSE-5C-E rev G	Elpida	48.16188.0 11 rev 1	Yes	(64Mx8)*9	SR	10/13/05
+Legacy Electronics Inc.	B557K4C2AAA-50	K4T51083QC-ZCCC rev C	Samsung	LE9DD2F2 408RRA rev A		(64Mx8)*9	SR	10/13/05
Nanya Technology Corporation*	NT512T72U89A0BV- 5A	NT5TU64M8AE-5A rev A	Nanya	NTPCB000 20P (0509) na	Yes	(64Mx8)*9	SR	10/17/05
+Ventura Technology Group	D2-52KC53SV-333	K4T56043QF-ZCD5 rev F	Samsung	D2R472 na		(64Mx4)*18	SR	9/30/05
+Kingston	KVR400D2S8R3/512 I	NT5TU64M8AE-37B rev A	Nanya	2025263- 001.C00 na		(64Mx8)*9	SR	11/2/05
Samsung	M393T6450FZ3-CCC	K4T56043QF-ZCCC	Samsung		Yes	(64Mx4)*18	SR	10/24/05
Samsung	M393T6553CZ3-CCC	K4T51083QC-ZCCC	Samsung		Yes	(64Mx8)*9	SR	11/4/05
Samsung	M393T6453FG3-CCC	K4T56083QF-GCCC	Samsung			(32Mx8)*18	DR	11/4/05

Registered, ECC, DDR2-400 DIMM Modules 512 MB Sizes (64Mx72)								
Manufacturer	Part Number	DRAM Part Number	DRAM Vendor	PCB Part Number	Lead Free	DRAM Organization	Rank	Date
Samsung	M393T6453FZ3-CCC	K4T56083QF-ZCCC	Samsung		Yes	(32Mx8)*18	DR	11/4/05
Samsung	M393T6450FG3-CCC	K4T56043QF-GCCC	Samsung			(64Mx4)*18	SR	11/4/05
+ATP Electronics	AH64K72F8BHC4S	K4T51083QC-ZCD5 rev C	Samsung	SH240F08K1 na	Yes	(64Mx8)*9	SR	12/05
+Apacer	75.963A1.G02	K4T51083QC-ZCD5 rev C	Samsung	48.16188.011 rev 1	Yes	(64Mx8)*9	SR	12/05
+Smart Modular Technologies	SG647RDR264835-SC	K4T51083QC-ZCCC rev C	Samsung	M393T6553BG1 (KS-11A)	Yes	(64Mx8)*9	SR	1/17/06
Hynix	HYMP564R72BP8-E3	HY5PS12821BFP-E3	Hynix		Yes	(64Mx8)*9	SR	1/10/06
Hynix	HYMP564R72P8-E3	HY5PS12821FP-E3	Hynix		Yes	(64Mx8)*9	SR	1/10/06
+Legend	L64723C7-R41H2H1F	HY5PS12821FP-E3 rev 1st Gen.	Hynix	104 (0530,0534)	Yes	(64Mx8)*9	SR	2/8/06
+Buffalo	D2R400A-ES512MBJ	MT47H64M8CB-5E rev B	Micron	2DRA18F-BA na	Yes	(64Mx8)*9	SR	2/23/06
+Dataram	DTM63312B	NT5TU64M8AE-37B rev A	Nanya	40042A rev A	Yes	(64Mx8)*9	SR	2/28/06
+Ventura Technology Group	D2-52KD65SV-333	K4T51083QC-ZCD5 rev C	Samsung	D2R18A na	Yes	(64Mx8)*9	SR	3/14/06
Transcend Information	TS64MQR72V4J	K4T51083QC-ZCCC rev C	Samsung	09-2140 na	Yes	(64Mx8)*9	SR	3/22/06
TRS	TRS31261	HYB18T256400AF5 rev A	Qimonda	M0549LA1 rev 1	Yes			04/05/06
TRS	TRS31260	HYB18T512800AF5 rev A	Qimonda	M0551LA1 rev 1	Yes			04/07/06
Dataram	DTM63311D	HYB18T256400AF5 rev A	Qimonda	40011A rev A	Yes			04/11/06
Buffalo	D2R400A-ES512MBJ	MT47H64M8CB-5E rev B	Micron	2DRA18F-BA na	Yes	(64Mx8)*9	SR	04/29/06
Kingston	KVR400D2S8R3/512 I	E5108AG-5C-E rev G	Elpida	2025263-001.C00 na	Yes	(64Mx8)*9	SR	7/7/06
TRS	TRS31260X	HYB18T512800AF5 rev A	Qimonda	M0551LA1 rev 1	Yes	(64Mx8)*9	SR	6/30/06
TRS	TRS31274	HYB18T512800AF37 rev A	Qimonda	M0551LA1 rev 1	Yes	(64Mx8)*9	SR	8/7/06
Super Talent Electronics	T400RA512/S12TR8 BHS	K4T51083QC-ZCD5 rev C	Samsung	DR20809 rev F1.01	Yes	(64Mx8)*9	SR	8/10/06
Super Talent Electronics	T400RA512/S12TR8 BHS	K4T51083QC-ZCD5 rev C	Samsung	DR20809 rev F1.01	Yes	(64Mx8)*9	SR	8/10/06
TRS	TRS31275	E5108AG-5C-E rev G	Elpida	M0551LA1 rev 1	Yes	(64Mx8)*9	SR	8/21/06
SimpleTech	S512R3RL1PK-I	E5108AGBG-5C-E rev G	Elpida	D2R872 na	Yes	(64Mx8)*9	SR	8/23/06
Corsair	CM72DD512AR-400/S	K4T51083QC-ZCD5 rev C	Samsung	50-00128B-G	Yes	(64Mx8)*9	SR	9/1/06
TRS	TRS31284	K4T51083QC-ZCD5 rev C	Samsung	M0551LA1 rev 1	Yes	(64Mx8)*9	SR	9/7/06
TRS	TRS31261X	HYB18T256400AF5 rev A	Qimonda	M0549LA1 rev 1	Yes	(64Mx8)*9	SR	9/14/06

**Registered, ECC, DDR2-400 DIMM Modules
512 MB Sizes (64Mx72)**

Manufacturer	Part Number	DRAM Part Number	DRAM Vendor	PCB Part Number	Lead Free	DRAM Organization	Rank	Date
Viking	VR5ER647218EBPA 1	HY5PS12821BFP-C4 rev B	Hynix	0000992A rev A	Yes	(64Mx8)*9	SR	10/18/06
Kingston	KVR400D2S8R3/512 I	E5108AGBG-6E-E rev G	Elpida	2025263- 001.C00 na	Yes	(64Mx8)*9	SR	11/9/06
Dataram	DTM63312E	HY5PS12821CFP-Y5 rev C	Hynix	40042A rev A	Yes	(64Mx8)*9	SR	4/26/07
Samsung	M393T6553EZ3- CCC	K4T51083QE	Samsung		Yes	(64Mx8)*9	SR	1/7/08

**Registered, ECC, DDR2-533 DIMM Modules
512 MB Sizes (64Mx72)**

Manufacturer	Part Number	DRAM Part Number	DRAM Vendor	PCB Part Number	Lead Free	DRAM Organization	Rank	Date
Micron	MT9HTF647FY- 53ED4	MT47H64M4B6- 37E:D	Micron		Yes	(64Mx4)* 18		1/11/07

**Registered, ECC, DDR2-667 DIMM Modules
512 MB Sizes (64Mx8)*9**

Micron	MT9HTF6472PY-667F1	MT47H64M8CF-3:F	Micron		Yes	(64Mx8)*9	1	9/22/08
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(+) This vendor is part of the CMTL Certification program. This means this part has/will be tested across all compatible Intel Server Boards. For further information contact CMTL @ <http://cmtlabs.com/>

Caution: Some modules on this list may contain "stacked" DRAM parts. These parts may have thermal & physical limitations in some chassis configurations. It is advised to verify that your chassis configuration will support "stacked" parts before purchase.

Verify that the DRAM part number matches the DRAM on this list before purchasing.

Intel® Server Board SE7520JR2
Registered, ECC, DDR-266 DIMM Modules
1GB Size (128M x 72)

Manufacturer	Part Number	DRAM Part Number	DRAM Vendor	PCB Part Number	Lead Free	DRAM Organization	Rank	Date
+TRS	TRS21174	HYB25D512800AT-7 rev A	Qimonda	M0529LA1 rev 1		(64Mx8)* 18	DR	9/9/04
+TRS	TRS21203	HYB25D512400BE-7 rev B	Qimonda	M0530LA1 rev 1		(128Mx4)*18	SR	10/18/04
Corsair	CM72SD1024RLP-2100/M	MT46V64M8TG(P)-6T rev C	Micron	50-00123 rev A		(64Mx8)*18	DR	10/13/04
+Ventura Technology Group	D54WYK42SV	K4H510838B-TCB3 rev B	Samsung	DR1G872-A		(64Mx8)*18	DR	11/1/04
+Swissbit*	SDR12872C1A22IN-70	HYB25D256400BC-7 rev B	Qimonda	B6R400 rev A		(64Mx4)*36	DR	11/15/04
+Swissbit	SDR12872K1A32IN-70	HYB25D256400CC-5 rev C	Qimonda	B6R404 rev 1		(64Mx4)*36	DR	3/8/05
+Legend	L1272YC5-RU1HDD5A	HY5DU12822AT-H rev A	Hyundai	DRR1U0818-A rev 1		(64Mx8)*18	DR	3/17/05
Hynix	HYMD512G726B4M-H	HY5DU12422BT-H	Hynix			(128Mx4)*18	SR	3/29/05
Micron	MT18VDDT12872G-265D2	MT46V128M4TG-6T	Micron			(128Mx4)*18	SR	4/1/05
+Dataram	DTM63698C	HYB25D512400BT(BE)-6 rev B	Qimonda	40581A rev A		(128Mx4)*18	SR	6/20/05
Samsung	M312L2828ET0-CB0	K4H510638E-TCB0	Samsung		Yes	(64Mx4)*36	DR	9/21/05
Samsung	M312L2920CUS-CB0	K4H510438C-UCB0	Samsung		Yes	(128Mx4)*18	SR	9/21/05
Samsung	M312L2828EZ0-CB0	K4H510638E-UCB0	Samsung		Yes	(64Mx4)*36	DR	9/26/05
+Legend	L1272YC5-183HDD5A	HY5DU56422AS-H rev A	Hyundai	184RL rev 3		(64Mx4)*36	DR	10/27/05
Samsung	M312L2828EU0-CB0		Samsung		Yes			9/26/05
+Dataram	DTM63653R	HYB25D256400CF-6 rev C	Qimonda	40599A rev A	Yes	(64Mx4)*36	DR	3/10/06
Wintec Industries	3C952684C-L	K4H510838C-UCCC rev C	Samsung	DR1G872 rev A	Yes	(64Mx8)*18	DR	05/05/06
Smart Modular Technologies	SG12872RDDR308BTSC	K4H510838C-UCCC rev C	Samsung	PG52G184NEBZ6RCL rev A	Yes	(64Mx8)*18	DR	05/19/06

Registered, ECC, DDR-333 DIMM Modules
1GB Size (128M x 72)

Manufacturer	Part Number	DRAM Part Number	DRAM Vendor	PCB Part Number	Lead Free	DRAM Organization	Rank	Date
Samsung	M312L2820EG0-CB3		Samsung	K4H560438E-GCB3	Yes	(64Mx4)*36	DR	7/20/04
+Smart Modular Technologies	SM12872RDDR6H2BGAI	HYB25D256400BC-6 rev B	Qimonda	P54G184NESZBRCD rev A		(64Mx4)*36	DR	8/30/04
Micron	MT18VDDF12872G-335D3	MT46V128M4FN-6	Micron			(128Mx4)*18	SR	8/30/04
Kingston	KVR333X72RC25/1G	HYB25D256400CC-6 rev C	Qimonda	2025247-001.A00		(64Mx4)*36	DR	9/3/04

**Registered, ECC, DDR-333 DIMM Modules
1GB Size (128M x 72)**

Manufacturer	Part Number	DRAM Part Number	DRAM Vendor	PCB Part Number	Lead Free	DRAM Organization	Rank	Date
+Smart Modular Technologies	SM12872RDDR6 H2BGIC	HYB25D2564 00CC-6 rev C	Qimonda	P54G184NESZ BRCD rev B		(64Mx4)*36	DR	9/8/04
+Smart Modular Technologies	SM12872RDDR6 H1BGAI	HYB25D5124 00BC-6 rev B	Qimonda	P52G184NESZ BGAX rev A		(128Mx4)*18	SR	9/14/04
+Smart Modular Technologies	SM12872RDDR6 H2BGAS	K4H560438E-GCB3 rev E	Samsung	P54G184NESZ BRCD rev B		(64Mx4)*36	DR	9/20/04
+Viking	VI4CR287224DB KL2	K4H560438E-GCB3 rev E	Samsung	0000972B		(64Mx4)*36	DR	9/30/04
+Centon Electronics	TOP02-E150	K4H560438E-GCB3 rev E	Samsung	CPCB/00571 rev G		(64Mx4)*36	DR	10/7/04
+Dataram	DTM63677F	HYB25D2564 00CC-6 rev C	Qimonda	40599A rev A		(64Mx4)*36	DR	10/4/04
+TRS	TRS21197	HYB25D2564 00CC-6 rev C	Qimonda	M0533LA1 rev 1		(64Mx4)*36	DR	10/22/04
+Smart Modular Technologies	SM12872RDDR6 H8BGIB	HYB25D5128 00BC-6 rev B	Qimonda	P51G184NEBZ BIB1 rev A		(64Mx8)*18	DR	10/18/04
+ATP Electronics	AB28L72Y4BFB3 C	HYB25D2564 00BC-5 rev B	Qimonda	SB184Y04L1		(64Mx4)*36	DR	10/21/04
+Swissbit	SDR12872C1A22 IN-60	HYB25D2564 00BC-6 rev B	Qimonda	B6R400 rev A		(64Mx4)*36	DR	11/9/04
+TRS	TRS21197	HYB25D2564 00CC-6 rev C	Qimonda	M0533LA1 rev 1		(64Mx4)*36	DR	10/22/04
+ATP Electronics	AB28L72L4BFB3 C	HYB25D5124 00BC-6 rev B	Qimonda	SB184L04L1		(128Mx4)*18	SR	11/3/04
+Wintec Industries	3C954641D-L	HYB25D2564 00CC-5 rev C	Qimonda	ZK4096M84RC JB		(64Mx4)*36	DR	11/2/04
Qimonda	HYS72D128320G BR-6-C	HYB25D2564 00CC-6	Qimonda			(64Mx4)*36	DR	11/5/04
+Legacy Electronics Inc.	89S6MDZR-1NDG	HYB25D5124 00BC-6 rev B	Qimonda	LE18DDF1844 R rev A		(128Mx4)*18	SR	12/20/04
Micron	MT36VDDF12872 G-335G3	MT46V64M4F G-6	Micron			(64Mx4)*36	DR	1/14/05
+Legacy Electronics Inc.	89S6JDGM-1NDG	HYB25D2564 00BC6 rev B	Qimonda	LE36DDF1844 RRF rev A		(64Mx4)*36	DR	1/25/05
+Swissbit	SDR12872K1A32I N-60	HYB25D2564 00CC-5 rev C	Qimonda	B6R404 rev 1		(64Mx4)*36	DR	1/28/05
Qimonda	HYS72D128321G BR-6-B	HYB25D5128 00BC-6 B	Qimonda			(64Mx8)*18	DR	2/2/05
+ATP Electronics	AB28L72L4BFB3 M	MT46V128M4 FN-5B rev D	Micron	SB184L04L1		(128Mx4)*18	SR	3/3/05
+ATP Electronics	AB28L72L4BFB3 S	K4H510438C-ZCB3 rev C	Samsung	SB184L04L1		(128Mx4)*18	SR	2/28/05
Qimonda	HYS72D128300G BR-6-B	HYB25D5124 00BC-6 B DRAM date code 0514	Qimonda			(128Mx4)*18	SR	3/21/05
+Ventura Technology Group	D54YFK44MV	MT46V128M4 FN-6 rev D	Micron	DR1G472B		(128Mx4)*18	SR	3/24/05
+Dane-Elec	DLD333R072285 M	MT46V128M4 FN-5B rev D	Micron	DR1G472B		(128Mx4)*18	SR	3/15/05
+Centon Electronics	TOP-002	MT46V128M4 BN-6 rev D	Micron	DR1G472B		(128Mx4)*18	SR	3/22/05
SimpleTech	ST72E4L128ML-C06E	HYB25D5124 00BC-6 rev B	Qimonda	01269 rev A		(128Mx4)*18	SR	3/31/05

**Registered, ECC, DDR-333 DIMM Modules
1GB Size (128M x 72)**

Manufacturer	Part Number	DRAM Part Number	DRAM Vendor	PCB Part Number	Lead Free	DRAM Organization	Rank	Date
+Ventura Technology Group	D54YFK44SV	K4H510438C-ZCB3 rev C	Samsung	DR1G472B		(128Mx4)*18	SR	4/14/05
+Avant Technology	AVM7228R38C5333K4-MTG	MT46V64M4F G-6 rev G	Micron	B6R400 rev 1		(64Mx4)*36	DR	4/22/05
+Avant Technology	AVM7228R53C5333K6-MTD	MT46V128M4 FN-6 rev D	Micron	RCE0020-01 rev 1		(128Mx4)*18	SR	4/22/05
+Viking	VI4CR287228EB KL1	MT46V64M8F N-6 rev D	Micron	0001003A		(64Mx8)*18	DR	5/5/05
+Dataram	DTM63694B	K4H510438C-ZCB3 rev C	Samsung	40018A rev A		(128Mx4)*18	SR	5/11/05
Samsung	M312L2920CZ0-CB3	K4H510438C-ZCB3	Samsung		Yes	(128Mx4)*18	SR	6/20/05
Samsung	M312L2820EZ0-CB3	K4H510438B-GCB3	Samsung		Yes	(64Mx4)*36	DR	6/20/05
+Kingston	KVR333S4R25/1 GI	HYB25D5124 00BC-6 rev B	Qimonda	2025318-001.A00 na		(128Mx4)*18	SR	6/27/05
+Kingston	KVR333D4R25/1 GI	K4H560438E-GCB3 rev E	Samsung	2025247-001.A00 na		(64Mx4)*36	DR	7/11/05
Samsung	M312L2923CZ0-CB3	K4H510838C-ZCB3	Samsung		Yes	(64Mx8)*18	DR	8/9/05
Hynix	HYMD512G726B F4N-J	HY5DU12422 BF-J	Hynix			(128Mx4)*18	SR	10/10/05
+Avant Technology	AVM7228R53C5333K6-NYBP	NT5DS128M4 BG-6K rev B	Nanya	RCE0020-01 rev 1		(128Mx4)*18	SR	10/25/05
Samsung	M312L2820EZ3-CB3	K4H510438B-ZCB3	Samsung		Yes	(64Mx4)*36	DR	11/15/05
Samsung	M312L2820EG3-CB3	K4H510438B-GCB3	Samsung		Yes	(64Mx4)*36	DR	11/15/05
Samsung	M312L2923CZ3-CB3	K4H510838C-ZCB3	Samsung		Yes	(64Mx8)*18	DR	11/15/05
Samsung	M312L2920CZ3-CB3	K4H510438C-ZCB3	Samsung		Yes	(128Mx4)*18	SR	11/15/05
Hynix	HYMD512G726C FP4N-J	HYMD512G7 26CF4N-J	Hynix		Yes	(128Mx4)*18	SR	11/15/05
Qimonda	HYS72D128321H BR-6-C	HYB25D5128 00CF-6	Qimonda		Yes	(64Mx8)*18	DR	1/31/06
Qimonda	HYS72D128300H BR-6-C	HYB25D5124 00CF-6	Qimonda		Yes	(128Mx4)*18	SR	1/31/06
+Legacy Electronics Inc.	89B6MDZR-1NDG	K4H510438C-ZCB3 rev C	Samsung	LE18DDF1844 R rev A		(128Mx4)*18	SR	2/14/06
+Legend	L1272YC6-PPXSMD1B	K4H510438B-GCB3 rev B	Samsung	M312L6420G0 na		(128Mx4)*18	SR	2/23/06
Dataram	DTM63694C	HYB25D5124 00CF-6 rev C	Qimonda	40018A rev A	Yes			03/31/06
TRS	TRS21196	HYB25D2564 00BC-6 rev B	Qimonda	M0533LA1 rev 1				04/24/06
TRS	TRS21229	HYB25D5124 00BC-6 rev B	Qimonda	M0545LA1 rev 1		(128Mx4)*18	SR	05/09/06
Kingston	KVR333D4R25/1 GI	HYB25D2564 00CF-5 rev C	Qimonda	2025247-001.A00 na	Yes	(128Mx4)*18	SR	05/11/06
Wintec Industries	3C954749C-L	K4H510438C-ZCB3 rev C	Samsung	DR1G472B na	Yes	(128Mx4)*18	SR	05/16/06

Registered, ECC, DDR-333 DIMM Modules 1GB Size (128M x 72)								
Manufacturer	Part Number	DRAM Part Number	DRAM Vendor	PCB Part Number	Lead Free	DRAM Organization	Rank	Date
Kingston	KVR333S4R25/1 GI	K4H510438C-ZCB3 rev C	Samsung	2025324-001.A00 na	Yes	(128Mx4)*18	SR	8/23/06
Avant Technology	AVM7228R53C53 33K6-NYC	NT5DS128M4 CG-5T rev C	Nanya	RCE0020-01 na	Yes	(128Mx4)*18	SR	10/2/06
Kingston	KVR333S4R25/1 GI	K4H510438C-ZCCC rev C	Samsung	2025324-001.A00 na	Yes	(128Mx4)*18	SR	10/5/06
Kingston	KVR333S4R25/1 GI	HYB25D5124 00CF-5 rev C	Qimonda	2025324-001.A00 na	Yes	(128Mx4)*18	SR	4/27/07
Kingston	KVR333S4R25/1 GI	HYB25D5124 00BF-5 rev B	Qimonda	2025324-001.A00 na	Yes	(128Mx4)*18	SR	9/27/07
Registered, ECC, DDR2-400 DIMM Modules 1GB Size (128M x 72)								
Manufacturer	Part Number	DRAM Part Number	DRAM Vendor	PCB Part Number	Lead Free	DRAM Organization	Rank	Date
Micron	MT18HTF12872Y-40EA2	MT47H128M8 FP	Micron		Yes	(128Mx4)*18	SR	9/22/04
+Dataram	DTM63310A	HYB18T5124 00AF5 rev A	Qimonda	40011A rev A		(128Mx4)*18	SR	10/15/04
+Smart Modular Technologies	SM1287RDR2124 35IA	HYB18T5124 00AC5 rev A	Qimonda	P54G240NESU BRCC rev A		(128Mx4)*18	SR	10/22/04
Hynix	HYMP512R724-E3 AA-A	HY5PS12421-F-E3	Hynix			(128Mx4)*18	SR	10/28/04
+Wintec Industries	39C931284B-L	K4T51083QB-GCD5 rev B	Samsung	D2R872		(64Mx8)*18	DR	11/9/04
+Smart Modular Technologies	SM1287RDR2124 35IA	HYB18T5124 00AC5 rev A	Qimonda	P54G240NESU BRCC rev A		(128Mx4)*18	SR	10/22/04
+Smart Modular Technologies	SM1287RDR2124 35SB	K4T51043QB-GCCC rev B	Samsung	P54G240NESU BRCC rev A		(128Mx4)*18	SR	11/17/04
+Wintec Industries	39S931281A-L	HYB18T5128 00AF5 rev A	Qimonda	D2R872		(64Mx8)*18	DR	11/18/04
+ATP Electronics	AH28K72M4BHC 4S	K4T51043QB-GCCC rev B	Samsung	SH240M04K1		(128Mx4)*18	SR	11/23/04
+Legacy Electronics Inc.	S512872M20A-50A	HYB18T5124 00AF(C)5 rev A	Qimonda	LE18DD2F2404 RRH rev 1		(128Mx4)*18	SR	11/24/04
+Smart Modular Technologies	SM1287RDR2124 3-5-I	HYB18T5124 00AC5 rev A	Qimonda	240-13-4		(128Mx4)*18	SR	11/30/04
+Dataram	DTM63310F	K4T51043QB-GCCC rev B	Samsung	40011A rev A		(128Mx4)*18	SR	12/9/04
Samsung	M393T2953BG0-CCC	K4T51083QB-GCCC	Samsung			(64Mx8)*18	DR	12/14/04
+Smart Modular Technologies	SM1287RDR2124 3-5-S	K4T51043QB-GCCC rev B	Samsung	M393T2950BG0		(128Mx4)*18	SR	12/23/04
+Apacer	75.072A1.564	K4T51043QB-GCCC rev B	Samsung	48.16189.011 rev 1		(128Mx4)*18	SR	12/21/04
+Smart Modular Technologies	SB1287RDR2124 35IA	HYB18T5124 00AF5 rev A	Qimonda	PB54G240NES UBRCC1 rev A		(128Mx4)*18	SR	1/7/05
Kingston	KVR400D2R3/1G	E5104AB-4A-E rev B	Elpida	2025248-001 rev 0.5		(128Mx4)*18	SR	1/14/05
Netlist Inc*	NLD127R212038-D32KSB	K4T51043QB-GCCC rev B	Samsung	0208-10 rev A		(128Mx4)*18	SR	2/2/05

Registered, ECC, DDR2-400 DIMM Modules 1GB Size (128M x 72)								
Manufacturer	Part Number	DRAM Part Number	DRAM Vendor	PCB Part Number	Lead Free	DRAM Organization	Rank	Date
Samsung	M393T2953BZ0-CCC	K4T51083QB-ZCCC	Samsung		Yes	(64Mx8)*18	DR	2/24/05
+Smart Modular Technologies	SM1287RDR2124 3-5-H	HY5PS12421 F-E3 rev A	Hynix	E72369		(128Mx4)*18	SR	2/16/05
Samsung	M393T2950BG0-CCC Date Code: 0521	K4T51043QB-GCCC	Samsung			(128Mx4)*18	SR	2/28/05
+Viking	VR5ER287214EB PL1	MT47H128M4 BT-37E rev A	Micron	0001009A rev A		(128Mx4)*18	SR	3/14/05
Samsung	M393T2953CZ0-CCC	K4T510830C-ZCCC	Samsung		Yes	(64Mx8)*18	DR	3/22/05
Netlist Inc	NLD127R21203F-D32KSB	K4T51043QB-ZCCC rev B	Samsung	0208-10 rev A	Yes	(128Mx4)*18	SR	3/16/05
+Legend	L12723C7-RCAH2HBF	HY5PS12821 F-E3 rev A	Hynix	B62RRCA rev A		(64Mx8)*18	DR	3/16/05
+Viking	VR5ER287214EB PL1	MT47H128M4 BT-37E rev A	Micron	0001009A rev A		(128Mx4)*18	SR	3/14/05
+Viking	VR5ER287218EB PL1	K4T51083QB-ZCD5 rev B	Samsung	0000992A rev A		(64Mx8)*18	DR	3/16/05
Samsung	M393T2950BZ0-CCC Date Code: 0521	K4T51043QB-ZCCC	Samsung		Yes	(128Mx4)*18	SR	4/14/05
Qimonda	HYS72T128000H R-5-A	HYB18T5124 00AF5	Qimonda		Yes	(128Mx4)*18	SR	4/27/05
+Ventura Technology Group	D2-54KF53SV-333	K4T51043QB-ZCCC rev B	Samsung	D2R472		(128Mx4)*18	SR	4/21/05
+Apacer	75.072A1.574	K4T51043QB-ZCCC rev B	Samsung	48.16189.011 rev 1		(128Mx4)*18	SR	4/18/05
+Netlist, Incorporated	NLD127R212038-D32KIA	HYB18T5124 00AF5 rev A	Qimonda	0208-10 rev A		(128Mx4)*18	SR	4/21/05
+Kingston	KVR400D2S4R3/1GI	E5104AE-5C-E rev E	Elpida	2025248-001.B00		(128Mx4)*18	SR	5/9/05
Transcend Information	TS128MQR72V4 K	K4T51043QB-GCCC rev B	Samsung	09-2090		(128Mx4)*18	SR	5/5/05
Corsair	CM73DD1024R-400/S	K4T51043QB-ZCD5 rev B	Samsung	50-00129 rev A		(128Mx4)*18	SR	5/25/05
+Wintec Industries	39S931341A-L	HYB18T5124 00AF5 rev A	Qimonda	D2R472		(128Mx4)*18	SR	6/1/05
+Apacer	78.01068.331	HYB18T5124 00AF5 rev A	Qimonda	48.16189.011 rev 1		(128Mx4)*18	SR	5/31/05
SimpleTech	ST72P4T128M-A05AU	K4T51043QB-ZCCC rev B	Samsung	E186014		(128Mx4)*18	SR	5/27/05
+Legacy Electronics Inc.	B512872M20A-50A	K4T51043QB-GCCC rev B	Samsung	LE18DD2F2404 RRRH rev A		(128Mx4)*18	SR	6/14/05
+Apacer	76.02220.B11	K4T51043QB-ZCCC rev B	Samsung	48.16189.011 rev 1		(128Mx4)*18	SR	6/27/05
+Viking	VR5ER287218EB PL3	MT47H64M8 CB-37E rev B	Micron	0000992A rev A		(64Mx8)*18	DR	6/24/05
+Smart Modular Technologies	SB1287RDR2124 3-5-H	HY5PS12421 FP-E3 A 1st Generation	Hynix	E72369 na		(128Mx4)*18	SR	7/14/05

**Registered, ECC, DDR2-400 DIMM Modules
1GB Size (128M x 72)**

Manufacturer	Part Number	DRAM Part Number	DRAM Vendor	PCB Part Number	Lead Free	DRAM Organization	Rank	Date
+Apacer	76.02220.B06	HYB18T512400AF5 rev A	Qimonda	48.16189.011 rev 1		(128Mx4)*18	SR	7/12/05
+Wintec Industries	39C931344B-GL	K4T51043QB-ZCCC rev B	Samsung	D2R472 na		(128Mx4)*18	SR	7/7/05
+Avant Technology	AVF7228R52E3400F0-MTB	MT47H64M8CB-37E rev B	Micron	50-1431-01B rev B		(64Mx8)*18	DR	6/29/05
Samsung	M393T2950CZ0-CCC	K45T1043QC-ZCCC	Samsung		Yes	(128Mx4)*18	SR	7/8/05
Qimonda	HYS72T128020HR-5-A	HYB18T512800AF5-A	Qimonda		Yes	(64Mx8)*18	DR	7/25/05
+Smart Modular Technologies	SB1287RDR21243-5-E	E5104AB-4A-E rev B	Elpida	Z10 026A na		(128Mx4)*18	SR	08/02/05
+Legacy Electronics Inc.	L512872M20A-50A	BGA128X4DDR2NC (DDR DAT)	Legacy	LE18DD2F2404RRH rev A		(128Mx4)*18	SR	08/17/05
Micron	MT18HTF12872Y-40EB3	MT47H64M8BT-5E	Micron		Yes	(128Mx4)*18	SR	8/19/05
+Kingston	KVR400D2S8R3/1GI	HYB18T1G800AF-5 rev A	Qimonda	2025263-001.C00		(128Mx8)*9	SR	8/30/05
+Dataram	DTM63327A	HYB18T512800AF5 rev A	Qimonda	40056A rev A		(64Mx8)*18	DR	9/16/05
+Wintec Industries	39931344B-L	K4T51043QB-GCCC rev B	Samsung	D2R472 na		(128Mx4)*18	SR	9/22/05
Samsung	M393T2950CZ3-CCC	K4T51043QC-ZCCC	Samsung		Yes	(128Mx4)*18	SR	9/30/05
+Corsair	CM73DD1024R-400/E	E5104AE-5C-E rev E	Elpida	50-00129 rev A		(128Mx4)*18	SR	9/29/05
+Kingston	KVR400D2S4R3/1GI	HYB18T512400AF5 rev A	Qimonda	2025248-001.B00 na		(128Mx4)*18	SR	10/18/05
+Legacy Electronics Inc.	C517M7A2AHA-50	NT5TU128M4AE-5A rev A	Nanya	LE18DD2F2404RRH rev A		(128Mx4)*18	SR	10/10/05
Nanya Technology Corporation	NT1GT72U4PA0BV-5A	NT5TU128M4AE-5A rev A	Nanya	NTPCB00019 (0519, 0515) na	Yes	(128Mx4)*18	SR	10/21/05
+Legacy Electronics Inc.	B517M4C2AHA-50	K4T51043QC-ZCCC rev C	Samsung	LE18DD2F2404RRH rev A		(128Mx4)*18	SR	10/27/05
+Smart Modular Technologies	SG1287RDR264835IA5	HYB18T512800AF5 rev A	Qimonda	PG58G240NEBUB2RB rev A		(64Mx8)*18	DR	11/4/05
+Smart Modular Technologies	SG1287RDR264835IA	HYB18T512800AF37 rev A	Qimonda	PG58G240NEBUB2RB rev A		(64Mx8)*18	DR	11/9/05
Hynix	HYMP512R72P8-E3		Hynix			(64Mx8)*18	DR	10/24/05
Samsung	M393T2953CZ3-CCC	K4T510830C-ZCCC	Samsung		Yes	(64Mx8)*18	DR	11/4/05
+Legacy Electronics Inc.	D2D1G400R72S4C3	HYB18T512400AF5 rev A	Qimonda	240-13-5	Yes	(128Mx4)*18	SR	12/20/05
+Apacer	75.072A1.G02	K4T51043QC-ZCD5 rev C	Samsung	48.16189.011 rev 1	Yes	(128Mx4)*18	SR	12/23/05
+Smart Modular Technologies	SG1287RDR264835SC	K4T51083QC-ZCD5 rev C	Samsung	PG58G240NEBUB2RB rev A	Yes	(64Mx8)*18	DR	1/5/06
+Kingston	KVR400D2S4R3/1GI	HYB18T512400AF37 rev A	Qimonda	2025248-001.B00 na	Yes	(128Mx4)*18	SR	1/12/06
Hynix	HYMP112R72P8-E3	HY5PS1G831FP-E3	Hynix		Yes	(128Mx8)*9	SR	1/10/06

**Registered, ECC, DDR2-400 DIMM Modules
1GB Size (128M x 72)**

Manufacturer	Part Number	DRAM Part Number	DRAM Vendor	PCB Part Number	Lead Free	DRAM Organization	Rank	Date
SimpleTech	ST72P4T128M-A05AU	K4T51043QC-ZCCC rev C	Samsung	D2R472 na	Yes	(128Mx4)*18	SR	1/20/06
+Dataram	DTM63310J	NT5TU128M4AE-5A rev A	Nanya	40011A rev A	Yes	(128Mx4)*18	SR	2/2/06
Hynix	HYMP512R72BP8-E3	HY5PS12821BFP-E3	Hynix		Yes	(64Mx8)*18		1/31/06
Hynix	HYMP512R72BP4-E3	HY5PS12421BFP-E3	Hynix		Yes	(128Mx4)*18	SR	1/31/06
Hynix	HYMP512R72P4-E3	HY5PS12421FP-E3	Hynix		Yes	(128Mx4)*18	SR	1/31/06
Legend	L12723C7-R41H2M1F	HY5PS12421F-E3 rev 1st Gen.	Hyundai	104		(128Mx4)*18	SR	2/14/06
+ATP Electronics	AH28K72M4BHC4S	K4T51043QC-ZCCC rev C	Samsung	SH240M04K2na	Yes	(128Mx4)*18	SR	2/17/06
+MDT Technologies	I924-402-18R	HYB18T512400AF5 rev A	Qimonda	240-13-5 na	Yes	(128Mx4)*18	SR	2/22/06
+Dataram	DTM63327B	NT5TU64M8AE-37B rev A	Nanya	40056A rev A	Yes	(64Mx8)*18	DR	2/27/06
+Kingston	KVR400D2S8R3/1GI	E1108AA-5C-E rev A	Elpida	2025263-001.C00 na	Yes	(128Mx4)*18	SR	3/2/06
+TRS	TRS31265	HYB18T512400AF5 rev A	Qimonda	M0549LA1 rev 1	Yes	(128Mx4)*18	SR	3/17/06
Transcend Information	TS128MQR72V4J	K4T51083QC-ZCD5 rev C	Samsung	09-2060 rev 1	Yes	(64Mx8)*18	DR	3/24/06
ATP Electronics	AH28K72L8BHC4S	K4T51083QC-ZCD5 rev C	Samsung	SH240L08K2na	Yes			04/11/06
Kingston	KVR400D2S8R3/1GI	E1108AA-5C-E rev A	Elpida	2025263-001.C00 na	Yes	(128Mx8)*9	SR	04/28/06
MDT Technologies	M924-402-18R	MDT18D51240D-5 na	MDT	B62RRCH1.01na		(128Mx4)*18	SR	05/19/06
Kingston	KVR400D2S4R3/1GI	NT5U128M4AE-5A rev A	Nanya	2025248-001.B00 na	Yes	(128Mx4)*18		6/09/06
Netlist, Inc.	NLD127R21203F-D32KNA	NT5TU128M4AE-5A rev A	Nanya	0208-10 rev B	Yes	(128Mx4)*18		6/23/06
Smart Modular Technologies	SG1287RDR212435NA	NT5TU128M4AE-5A rev A	Nanya	NTPCB00019P	Yes	(128Mx4)*18		7/05/06
TRS	TRS31267	K4T51043QC-ZCCC rev C	Samsung	M0549LA1 rev 1	Yes	(128Mx4)*18		7/03/06
Dane-Elec	DMD400R072283NG	EDE5108AESK-5C-E rev E	Elpida	D2R872 rev 1	Yes	(64Mx8)*18		7/24/06
Super Talent Electronics	T400RA1G4/S1GTR4BHS	K4T51043QC-ZCD5 rev C	Samsung	DR20418 rev H1.01	Yes	(128Mx4)*18	SR	8/16/06
Super Talent Electronics	T400RB1G/S1GTR8CHS	K4T51083QC-ZCD5 rev C	Samsung	DR20818 rev G1.01	Yes	(64Mx8)*18	DR	8/22/06
TRS	TRS31277	E5104AG-5C-E rev G	Elpida	M0549LA1 rev 1	Yes	(128Mx4)*18	SR	8/30/06
Avant Technology	AVF7228R52E3400F0-MTDP	MT47H64M8B6-37E rev D	Micron	50-1431-01B rev B	Yes	(64Mx8)*18	DR	9/6/06
TRS	TRS31276	HYB18T512400AF37 rev A	Qimonda	M0549LA1 rev 1	Yes	(128Mx4)*18	SR	9/11/06
TRS	TRS31265X	HYB18T512400AF5 rev A	Qimonda	M0549LA1 rev 1	Yes	(128Mx4)*18	SR	9/12/06

**Registered, ECC, DDR2-400 DIMM Modules
1GB Size (128M x 72)**

Manufacturer	Part Number	DRAM Part Number	DRAM Vendor	PCB Part Number	Lead Free	DRAM Organization	Rank	Date
Kingston	KVR400D2S4R3/1GI	E5104AG-5C-E rev G	Elpida	2025248-001.B00 na	Yes	(128Mx4)*18	SR	10/9/06
Viking	VR5ER287218EB PA1	HY5PS12821 BFP-C4 rev B	Hyundai	0000992A rev A	Yes	(64Mx8)*18	DR	10/20/06
Avant Technology	AVF7228R53E34 00F0-ELEP	EDE5104AE-5C-E rev E	Elpida	50-1435-01B rev B	Yes	(128Mx4)*18	SR	11/10/06
Kingston	KVR400D2S8R3/1GI	E1108AB-6E-E rev B	Elpida	2025263-001.C00 na	Yes	(128Mx8)*9	SR	11/22/06
Micron	MT18HTF12872Y-40ED6	MT47H128M4 B6-37E:D	Micron		Yes	(128Mx4)*18	SR	1/11/07
TRS	TRS31277X	E5104AG-5C-E rev G	Elpida	M0549LA1 rev 1	Yes	(128Mx4)*18	SR	2/6/07
All Components	AVF7228R53E34 00F0-ELEP	EDE5104AE-5C-E rev E	Elpida	50-1435-01B rev B	Yes	(128Mx4)*18	SR	2/22/07
US Technology	AVF7228R53E34 00F0-ELEP	EDE5104AE-5C-E rev E	Elpida	50-1435-01B rev B	Yes	(128Mx4)*18	SR	3/24/07
Kingston	KVR400D2S8R3/1GI	MT47H128M8 HQ-3 rev E	Micron	2025263-001.C00 na	Yes	(128Mx8)*9	SR	4/19/07
Dataram	DTM63310N	HY5PS12421 CFP-Y5 rev C	Hynix	40011A rev A	Yes	(128Mx4)*18	SR	4/23/07
Dataram	DTM63327C	HY5PS12821 CFP-Y5 rev C	Hynix	40056A rev A	Yes	(64Mx8)*18	DR	4/25/07
Kingston	KVR400D2S4R3/1GI	E5104AHSE-6E-E rev H	Elpida	2025248-001.B00 na	Yes	(128Mx4)*18	SR	4/30/07
Ventura Technology Group	D2-54KD50SV-333	K4T51083QE-ZCE6 rev E	Samsung	D2R28G na	Yes	(64Mx8)*18	DR	7/27/07
Smart Modular Technologies	SG1287RDR2124 35IB	HYB18T5124 00BF37 rev B	Qimonda	PG54G240NES UBRCC1 rev A	Yes	(128Mx4)*18	SR	10/22/07
Kingston	KVR400D2S4R3/1GI	NT5TU128M4 BE-3C rev B	Nanya	2025248-001B00	Yes	(128Mx4)*18	SR	12/19/07
Samsung	M393T2950EZ3-CCC	K4T51043QE	Samsung		Yes	(128Mx4)*18	SR	1/7/08
Micron	MT9HTF12872PY-667E1	MT47H128M8 HQ-3:E	Micron		Yes	(128Mx8)*9	1	3/3/08
Kingston	KVR400D2S4R3/1GI	HYB18T5124 00B2F25F rev B2	Qimonda	2025248-001.B00	Yes	128M x 4	1	06/04/08
Kingston	KVR400D2S8R3/1GI	E1108ACBG-8E-E rev C	Elpida	2025263-001.C00	Yes	128M x 8	1	06/12/08

(+) This vendor is part of the CMTL Certification program. This means this part has/will be tested across all compatible Intel Server Boards. For further information contact CMTL @ <http://cmtlabs.com/>

Caution: Some modules on this list may contain "stacked" DRAM parts. These parts may have thermal & physical limitations in some chassis configurations. It is advised to verify that your chassis configuration will support "stacked" parts before purchase.

Verify that the DRAM part number matches the DRAM on this list before purchasing.

Intel® Server Board SE7520JR2
Registered, ECC, DDR-266 DIMM Modules
2GB Size (256M x 72)

Manufacturer	Part Number	DRAM Part Number	DRAM Vendor	PCB Part Number	Lead Free	DRAM Organization	Rank	Date
+TRS	TRS21155	HYB25D512400AT-7 rev A	Qimonda	M0531LA1 rev 1		(128Mx4)*36	DR	10/7/04
+Ventura Technology Group	D56WXX28SV	K4H510438B-TCB3 rev B	Samsung	V213		(128Mx4)*36	DR	11/4/04
Kingston	KVR266X72RC25 /2G	K4H510438B-TCB0 rev B	Samsung	2025148-001.A00		(128Mx4)*36	DR	11/18/04
+Viking	VI4CR567224EY HL3	K4H510438B-TCB3 rev B	Samsung	03-0307 rev B		(128Mx4)*36	DR	12/20/04
+Dataram	DTM63710A	HYB25D512400BE-7 rev B	Qimonda	40028A rev A		(128Mx4)*36	DR	1/12/05
+ATP Electronics	AB56L72T4SHB0 S	K4H510438B-TCB3 rev B	Samsung	SB184T04L3		(128Mx4)*36	DR	1/18/05
+Dataram	DTM63689D	HYB25D512400BF(BC)-6 rev B	~ Qimonda (Infineon)	40020A rev A		(128Mx4)*36	DR	5/31/05
+Avant Technology	AVM7256R53C52 66K7-MTD	MT46V128M4FN-6 rev D	Micron	E186014		(128Mx4)*36	DR	6/3/05
Samsung	M312L5628BT0-CB0	K4H1G0638B-TCB0	Samsung		Yes	(128Mx4)*36	DR	6/20/05
+TRS	TRS21218	HYB25D512400BE-7 rev B	Qimonda	M0531LA1 rev 1		(128Mx4)*36	DR	7/27/05
+Wintec Industries	35962841-L	HYB25D1G400AE-7 rev A	Qimonda	85616648 na		(256Mx4)*18	SR	7/18/05
Samsung	M312L5628CU0-CB0	K4H1G0638C-UCB0	Samsung		Yes	(128Mx4)*36	DR	8/19/05
Micron	MT36VDDF25672 G-265D2	MT46V128M4FN	Micron			(128Mx4)*36	DR	9/12/05

Registered, ECC, DDR-333 DIMM Modules
2GB Size (256M x 72)

Manufacturer	Part Number	DRAM Part Number	DRAM Vendor	PCB Part Number	Lead Free	DRAM Organization	Rank	Date
Smart	SM25672RDDR6 H2BGAI	SM25672RDDR6H2 BGAI	Qimonda			(128Mx4)*36	DR	7/29/04
+Dataram	DTM63680F	HYB25D512400BF-6 rev B	Qimonda	40020A rev A		(128Mx4)*36	DR	9/10/04
+Wintec Industries	35964741-L	HYB25D512400BC-6 rev B	Qimonda	85616658		(128Mx4)*36	DR	10/15/04
Micron	MT36VDDF25672 G-335D2	MT46V128M4FN	Micron			(128Mx4)*36	DR	12/16/04
+Legacy Electronics Inc.	8AL6MDGM-1PDG	BGA128MX4DDRNC	Legacy	LE36DDF1844 RRF rev B		(128Mx4)*36	DR	12/6/04
+Smart Modular Technologies	SM25672RDDR6 H2BGBI	HYB25D512400BC-6 rev B	Qimonda	184-25-2		(128Mx4)*36	DR	1/11/05
+ATP Electronics	AB56L72Z4BFB3 C	HYB25D512400BC-6 rev B	Qimonda	SB184Z04L1		(128Mx4)*36	DR	1/18/05
+ATP Electronics	AB56L72Z4BFB3 S	K4H510438C-ZCB3 rev C	Samsung	SB184Z04L1		(128Mx4)*36	DR	2/21/05

Registered, ECC, DDR-333 DIMM Modules 2GB Size (256M x 72)								
Manufacturer	Part Number	DRAM Part Number	DRAM Vendor	PCB Part Number	Lead Free	DRAM Organization	Rank	Date
+Kingston	KVR333D4R25/2 GI	HYB25D512400BC-6 rev B	Qimonda	2025294-001.A00		(128Mx4)*36	DR	4/7/05
+Avant Technology	AVM7256R53C53 33K7-MTD	MT46V128M4FN-6 rev D	Micron	B6R404 rev 1		(128Mx4)*36	DR	5/9/05
+Smart Modular Technologies	SG25672RDDR6 H2BGSC	K4H510438C-ZCB3 rev C	Samsung	PG54G184NES ZB1RF rev A		(128Mx4)*36	DR	5/23/05
Samsung	M312L5720CZ0-CB3		Samsung		Yes	(128Mx4)*36	DR	6/20/05
Qimonda	HYS72D256320G BR-6-B	HYB25D512400BC-6 B	Qimonda			(128Mx4)*36	DR	7/8/05
+Legacy Electronics Inc.	8AB6MDGM-1NDG	K4H510438C-ZCB3 rev C	Samsung	LE36DDF1844 RRF rev B		(128Mx4)*36	DR	08/10/05
+Viking	VR4CR567224EB KL1	HYB25D512400CF-6 rev C	Qimonda	0001010B rev B		(128Mx4)*36	DR	9/15/05
+Kingston	KVR333D4R25/2 GI	MT46V128M4FN-6 rev D	Micron	2025294-001.A00 na		(128Mx4)*36	DR	11/21/05
Samsung	M312L5720CZ3-CB3	M312L2920CZ3-CB3	Samsung		Yes	(128Mx4)*36	DR	11/15/05
Qimonda	HYS72D256320H BR-6-C	HYB25D512400CF-6	Qimonda		Yes	(128Mx4)*36	DR	1/31/06
+Dataram	DTM63680P	HYB25D512400CF-6 rev C	Qimonda	40020A rev A	Yes	(128Mx4)*36	DR	3/24/06
TRS	TRS21225	HYB25D512400BC-6 rev B	Qimonda	M0546LA1 rev 1				04/14/06
Kingston	KVR333D4R25/2 GI	K4H510438C-ZCB3 rev C	Samsung	2025294-001.A00 na	Yes	(128Mx4)*36	DR	7/24/06
Kingston	KVR333D4R25/2 GI	HYB25D512400CF-5 rev C	Qimonda	2025294-001.A00 na	Yes	(128Mx4)*36	DR	4/13/07
Kingston	KVR333D4R25/2 GI	HYB25D512400BF-5 rev B	Qimonda	2025294-001.A00 na	Yes	(128Mx4)*36	DR	9/25/07
Registered, ECC, DDR2-400 DIMM Modules 2GB Size (256M x 72)								
Manufacturer	Part Number	DRAM Part Number	DRAM Vendor	PCB Part Number	Lead Free	DRAM Organization	Rank	Date
+Smart Modular Technologies	SM2567RDR2128 3-5-I	HYB18T512400AC5 rev A	Qimonda	240-20-1		(128Mx4)*36	DR	11/12/04
+Legacy Electronics Inc.	S525672M20A-50A	HYB18T512400AF5 rev A	Qimonda	TTM-SA2 rev 1		(128Mx4)*36	DR	11/2/04
Samsung	M393T5660MZ0-CCC	K4T1G044QM-ZCCC	Samsung		Yes	(256Mx4)*18	SR	11/29/04
+Dataram	DTM63309A	HYB18T512400AF5 rev A	Qimonda	40040A rev A		(128Mx4)*36	DR	12/1/04
+Legacy Electronics Inc.	8AL6MDGM-1PDG	BGA128MX4DDRNC	Legacy	LE36DDF1844 RRF rev B		(128Mx4)*36	DR	12/6/04
Micron	MT18HTF25672Y -40EA2		Micron		Yes	(256Mx4)*18	SR	12/13/04
+Smart Modular Technologies	SM2567RDR2128 3-5-S	K4T51043QB-SCCC rev B	Samsung	M393T5750BS 1		(128Mx4)*36	DR	12/27/04

**Registered, ECC, DDR2-400 DIMM Modules
2GB Size (256M x 72)**

Manufacturer	Part Number	DRAM Part Number	DRAM Vendor	PCB Part Number	Lead Free	DRAM Organization	Rank	Date
Samsung	M393T5750BS0-CCC Date Code: 0521	K45T1043QB-SCCC	Samsung			(128Mx4)*36	DR	1/10/05
Samsung	M393T5750BY0-CCC Date Code: 0521	K45T1043QB-ZCCC	Samsung		Yes	(128Mx4)*36	DR	2/24/05
+Dataram	DTM63320A	HYB18T1G400AF-5 rev A	Qimonda	40011A rev A		(256Mx4)*18	SR	3/10/05
+Smart Modular Technologies	SB2567RDR2128351A	HYB18T512400AF5 rev A	Qimonda	PB52G240NESUB1RJ		(128Mx4)*36	DR	2/28/05
+ATP Electronics	AH56K72M4BJC4M	MT47H256M4BT-5E rev A	Micron	SH240M04K1		(256Mx4)*18	SR	3/7/05
+ATP Electronics	AH56K72J4BHC4C	HYB18T512400AF5 rev A	Qimonda	SH240J04K1		(128Mx4)*36	DR	3/24/05
+Smart Modular Technologies	SM2567RDR22543-5-I	HYB18T1G400AF-5 rev A	Qimonda	240-13-5		(256Mx4)*18	SR	3/30/05
+Smart Modular Technologies	SM2567RDR22543-5-S	K4T1G044QM-ZCCC rev M	Samsung	M393T2950BG0		(256Mx4)*18	SR	4/15/05
Netlist, Incorporated	NLD257R212038-D32KIA	HYB18T512400AF5 rev A	Qimonda	0203-10 rev A		(128Mx4)*36	DR	4/18/05
Qimonda	HYS72T256000HR-5-A	HYB18T1G400AF-5	Qimonda		Yes	(256Mx4)*18	SR	5/4/05
+Kingston	KVR400D2D8R3/2GI	HYB18T1G800AF-5 rev A	Qimonda	2025302-001.A00 na		(128Mx8)*18	DR	08/11/05
Micron	MT36HTF25672Y-40EB1		Micron		Yes			8/19/05
Samsung	M393T5750CZ0-CCC	K45T1043QC-ZCCC	Samsung		Yes	(128Mx4)*36	DR	9/20/05
+Kingston	KVR400D2D4R3/2GI	E5104AE-5C-E rev E	Elpida	2025292-001.A00		(128Mx4)*36	DR	5/3/05
+Smart Modular Technologies	SG2567RDR2128351A	HYB18T512400AF5 rev A	Qimonda	PG52G240NESUB1RJ rev A		(128Mx4)*36	DR	6/10/05
Samsung	M393T5750CZ0-CCC	K45T1043QC-ZCCC	Samsung		Yes	(128Mx4)*36	DR	9/20/05
+Apacer	76.A2220.B10	HYB18T512400AF5 rev A	Qimonda	48.1A189.012 rev 2		(128Mx4)*36	DR	6/16/05
+Dataram	DTM63309B	K4T51043QC-ZCCC rev C	Samsung	40040A rev A		(128Mx4)*36	DR	7/25/05
+Wintec Industries	39C941441A-L	HYB18T1G400AF-5 rev A	Qimonda	D2R472 na		(256Mx4)*18	SR	7/1/05
+ATP Electronics	AH56K72M4BJC4C	HYB18T1G400AF-3.7 rev A	Qimonda	SH240M04K1 na		(256Mx4)*18	SR	10/5/05
+Smart Modular Technologies	SG2567RDR21283-5-H	HY5PS1G421MP-E3 rev A	Hynix	0518-1,-2,-3,-4,-6	Yes	(256Mx4)*18	SR	10/10/05
+ATP Electronics	AH56K72M4BJC4C	HYB18T1G400AF-5 rev A	Qimonda	SH240M04K1 na	Yes	(256Mx4)*18	SR	10/31/05

**Registered, ECC, DDR2-400 DIMM Modules
2GB Size (256M x 72)**

Manufacturer	Part Number	DRAM Part Number	DRAM Vendor	PCB Part Number	Lead Free	DRAM Organization	Rank	Date
Nanya Technology Corporation	NT2GT72U4NA1 BV-5A	NT5TU128M4AE-5A rev A	Nanya	NTPCB00037P (0514) na	Yes	(128Mx4)*36	DR	10/19/05
Hynix	HYMP125R72P4-E3	HY5PS1G431FP-E3	Hynix			(256Mx4)*18	SR	10/24/05
Samsung	M393T5750CZ3-CCC	K45T1043QC-ZCCC	Samsung		Yes	(128Mx4)*36	DR	11/4/05
Samsung	M393T5660MZ3-CCC	K4T1G044QM-ZCCC	Samsung		Yes	(256Mx4)*18	SR	11/4/05
+Kingston	KVR400D2D4R3/2GI	HYB18T512400AF5 rev A	Qimonda	2025292-001.B00 na		(128Mx4)*36	DR	11/11/05
+Legacy Electronics Inc.	B527M4C2BJA-50	K4T51043QC-ZCCC rev C	Samsung	LE36DD2F240 4RRJ rev B		(128Mx4)*36	DR	11/23/05
+Legacy Electronics Inc.	D2D2G400R72S4 C3	HYB18T1G400AF-5 rev A	Qimonda	240-13-5	Yes	(256Mx4)*18	SR	12/21/05
+Legend	L25723C7-R41H2W2F	HY5PS1G421MP-E3 rev 1st Gen.	Hynix	0536	Yes	(256Mx4)*18	SR	1/17/06
Samsung	M393T5660AZ3-CCC	K4T1G044QA-ZCCC	Samsung		Yes	(256Mx4)*18	SR	12/13/05
+Kingston	KVR400D2D4R3/2GI	HYB18T512400AF3 7 rev A	Qimonda	2025292-001.B00 na	Yes	(128Mx4)*36	DR	1/26/06
Hynix	HYMP525R72BP4-E3	HY5PS12421BFP-E3	Hynix		Yes	(128Mx4)*36	DR	1/31/06
Hynix	HYMP125R72P8-E3	HY5PS1G831FP-E3	Hynix		Yes	(128Mx8)*18		1/31/06
+MDT Technologies	I948-402-18R	HYB18T1G400AF-5 rev A	Qimonda	240-13-5 na	Yes	(256Mx4)*18	SR	2/21/06
+Legacy Electronics Inc.	L527R5A2AHA-50X	256MX4DDR2MDT rev A	Legacy	LE18DD2F240 4RRH rev A		(256Mx4)*18	SR	3/7/06
+Kingston	KVR400D2D8R3/2GI	E1108AA-5C-E rev A	Elpida	2025302-001.A00 na	Yes	(128Mx4)*36	DR	3/10/06
TRS	TRS31270	HYB18T1G400AF-5 rev A	Qimonda)	M0549LA1 rev 1	Yes			03/31/06
Transcend Information	TS256MQR72V4T	E1104AA-4A-E rev A	Elpida	09-2090 rev 1	Yes	(256Mx4)*18	SR	05/22/06
Kingston	KVR400D2D8R3/2GI	E1108AA-5C-E rev A	Elpida	2025302-001.A00 na	Yes	(128Mx8)*18		05/09/06
Kingston	KVR400D2D4R3/2GI	NT5TU128M4AE-5A rev A	Nanya	2025292-001.B00 na	Yes	(128Mx4)*36		6/16/06
TRS	TRS31270X	HYB18T1G400AF-5 rev A	Qimonda	M0549LA1 rev 1	Yes	(256Mx4)*18	SR	8/3/06
Super Talent Electronics	T400RB2G4/S2G TR4CHS	K4T51043QC-ZCD5 rev C	Samsung	BA2RRCJ na	Yes	(128Mx4)*36	DR	8/23/06
Smart Modular Technologies	SG2567RDR2254 35-S	K4T1G044QA-ZCCC rev A	Samsung	M393T2950BG 1 na	Yes	(256Mx4)*18	SR	9/12/06
Kingston	KVR400D2D4R3/2GI	E5104AG-5C-E rev G	Elpida	2025292-001.B00 na	Yes	(128Mx4)*36	DR	10/10/06
Ventura Technology Group	D2-56KJ53LV-333	EDE1104AASE-5C-E rev A	Elpida	D2R472 na	Yes	(256Mx4)*18	SR	11/29/06
Smart Modular Technologies	SG2567RDR2124 35NB	NT5TU128M4BE-3C rev B	Nanya	PG52G240NES UB3RJ rev A	Yes	(128Mx4)*36	DR	12/1/06
Kingston	KVR400D2D8R3/2GI	E1108AB-6E-E rev B	Elpida	2025302-001.A00 na	Yes	(128Mx8)*18		12/11/06

**Registered, ECC, DDR2-400 DIMM Modules
2GB Size (256M x 72)**

Manufacturer	Part Number	DRAM Part Number	DRAM Vendor	PCB Part Number	Lead Free	DRAM Organization	Rank	Date
Legacy Electronics Inc.	L527R5A2AHA-50R	256MX4DDR2MDT5.0 rev A	Legacy	LE18D2FG34R RH rev A	Yes	(256Mx4)*18	SR	1/11/07
STEC Inc	INT72P4M256M8M-A05AYU	HYB18T512400AF37 rev A	Qimonda	01229 rev A	Yes	(128Mx4)*36	DR	4/6/07
Kingston	KVR400D2D8R3/2GI	MT47H128M8HQ-3 rev E	Micron	2025302-001.A00 na	Yes	(128Mx8)*18		4/17/07
Kingston	KVR400D2D4R3/2GI	E5104AHSE-6E-E rev H	Elpida	2025292-001.C00 na	Yes	(128Mx4)*36	DR	4/27/07
Dataram	DTM63309J	HY5PS12421CFP-Y5 rev C	Hynix	40040A rev A	Yes	(128Mx4)*36	DR	5/1/07
Smart Modular Technologies	SG2567RDR2124351B	HYB18T512400BF3S rev B	Qimonda	PG52G240NES UB3RJ rev A	Yes	(128Mx4)*36	DR	10/2/07
Smart Modular Technologies	SG2567RDR212435SE	K4T51043QE-ZCE6 rev E	Samsung	PG52G240NES UB3RJ rev A	Yes	(128Mx4)*36	DR	10/19/07
Kingston	KVR400D2D4R3/2GI	NT5TU128M4BE-3C rev B	Nanya	2025292-001.C00 na	Yes	(128Mx4)*36	DR	12/20/07
Kingston	KVR400D2D8R3/2GI	HY5PS1G831CFP-Y5 rev C	Hynix	2025302001.A00 na	Yes	(128Mx8)*18		2/27/08
Dataram	DTM63320B	HYB18T1G400BF-3.7 rev B	Qimonda	40011A rev A	Yes	(256Mx4)*18	SR	5/30/08
Dataram	DTM63309K	HYB18T512400B2F3S rev B2	Qimonda	40040A rev A	Yes	128M x 4	2	6/03/08
Kingston	KVR400D2D4R3/2GI	HYB18T512400B2F25F rev B2	Qimonda	2025292-001.C00	Yes	128M x 4	2	6/05/08
Kingston	KVR400D2D8R3/2GI	E1108ACBG-8E-E rev C	Elpida	2025302-001.A00	Yes	128M x 8	2	6/23/08

(+) This vendor is part of the CMTL Certification program. This means this part has/will be tested across all compatible Intel Server Boards. For further information contact CMTL @ <http://cmtlabs.com/>

Caution: Some modules on this list may contain "stacked" DRAM parts. These parts may have thermal & physical limitations in some chassis configurations. It is advised to verify that your chassis configuration will support "stacked" parts before purchase.

Verify that the DRAM part number matches the DRAM on this list before purchasing.

Intel® Server Board SE7520JR2
Registered, ECC, DDR-266 DIMM Modules
4GB Size (256M x 72)

Manufacturer	Part Number	DRAM Part Number	DRAM Vendor	PCB Part Number	Lead Free	DRAM Organization	Rank	Date
Micron	MT36VDDT51272G-265A2	MT46V256M4TG-75A	Micron			(256Mx4)*36	DR	4/15/05
Samsung	M312L5128MT0-CB0	K4H2G0638M-TCB0	Samsung			(256Mx4)*36	DR	6/20/05
+Dataram	DTM63687C	K4H1G0438M-TCB0 rev M	Samsung	40556 rev B		(256Mx4)*36	DR	08/15/05
+Smart Modular Technologies	SM51272RDDR3H1LP-S	K4H2G0638M-TCB0 rev M	Samsung	M312L2828T0		(256Mx4)*36	DR	11/9/05
Smart Modular Technologies	SM51272RDDR3H2LP-S	K4H1G0438M-TCB3 rev M	Samsung	M312L2828T0na		(256Mx4)*36	DR	8/25/06

Registered, ECC, DDR2-400 DIMM Modules
4GB Size (256M x 72)

Manufacturer	Part Number	DRAM Part Number	DRAM Vendor	PCB Part Number	Lead Free	DRAM Organization	Rank	Date
+Smart Modular Technologies	SG5127RDR225635IA	HYB18T1G400AF-5 rev A	Qimonda	PG516G240NE SUC1RK rev A		(256Mx4)*36	DR	9/27/05
Hynix	HYMP351R72MP4-E3		Hynix			(256Mx4)*36	DR	10/24/05
Qimonda	HYS72T512022HR-5-A	HYB18T2G402AF-5-A	Qimonda		Yes	(2x256Mx4)*18		11/1/05
+Kingston	KVR400D2D4R3/4GI	E1104AA-4A-E rev A	Elpida	2025343-001.A00 na		(256Mx4)*36	DR	11/15/05
+Kingston	KVR400D2D4R3/4GI	K4T2G064QA-ZCD5 rev A	Samsung	M393T1G68MG1 na	Yes	(256Mx4)*36	DR	3/15/06
Dataram	DTM63325A	HYB18T1G400AF-5 rev A	Qimonda	40054A rev D	Yes			04/07/06
Dataram	DTM63325A	HYB18T1G400AF-5 rev A	Qimonda	40054A rev D	Yes	(256Mx4)*36	DR	05/16/06
Smart Modular Technologies	SG5127RDR225635ART	HYB18T1G400AF-5 rev A	Qimonda	XG58G240NES UB1TK rev A	Yes	(256Mx4)*36	DR	1/5/07
Samsung	M393T5168AZ0-CCC	K4T2G264QA	Samsung		Yes	(512Mx4)*18		1/29/07
Kingston	KVR400D2D4R3/4GI	E1108ABSH-E rev B	Elpida	Z10077 na	Yes	(256Mx4)*36	DR	2/22/07
Dataram	DTM63353A	MT47H256M4HQ-37E rev E	Micron	40080A rev A	Yes	(256Mx4)*36	DR	4/4/07
Legacy Electronics Inc.	M547RAE20LA-50R	MT47H256M4HQ-3 rev E	Micron	D2R24L rev E	Yes	(256Mx4)*36	DR	4/24/07

(+) This vendor is part of the CMTL Certification program. This means this part has/will be tested across all compatible Intel Server Boards. For further information contact CMTL @ <http://cmtlabs.com/>

Caution: Some modules on this list may contain "stacked" DRAM parts. These parts may have thermal & physical limitations in some chassis configurations. It is advised to verify that your chassis configuration will support "stacked" parts before purchase.

Verify that the DRAM part number matches the DRAM on this list before purchasing.

4. Sales Information

Vendor Name	Web URL	Vendor Direct Sales Info
ATP Electronics	http://www.atpinc.com/	Tel (1) 408-732-5000, ext 5858 Fax 408-732-5893 sales@atpusa.com
ATP Electronics -- Taiwan Inc.	http://www.atpinc.com/	Tel 011-886-2-2659-6368 Fax 886-2-2659-4982
Avant Technology	http://www.avanttechnology.com	Brad Scoggins Phone: (512)491-7411 Fax: (512)491-7412 brads@avanttechnology.com
Aved Memory Products	http://www.avedmemory.com/	
Buffalo Technology	http://www.buffalotech.com/	(800) 967-0959 memory@buffalotech.com
Centon Electronics	http://www.centon.com	Tel: 949-855-9111 Fax: 949-855-6035
Corsair	http://www.corsairmicro.com/	Tel: 510-657-8747 Fax: 510-657-8748
Dane-Elec	http://www.dane-memory.com/	Michal Hassan @ (949)450-2941 or email @ Michal@Dane-memory.com
Dataram	http://www.dataram.com/	Paul Henke, 800-328-2726 x2239 in USA 609-799-0071 phenke@dataram.com
GoldenRAM	http://www.goldenram.com	Jason M. Barrette @ 800-222-861 x7546 jasonb@goldenram.com or Michael E. Meyer @800-222-8861 x7512 michaelm@goldenram.com
Hitachi	http://semiconductor.hitachi.com/pointer/	
Hyundai/Hynix Semiconductor	http://www.hea.com/	
~ Qimonda (Infineon)	http://www.infineon.com/business/distribut/index.htm	
ITAUCOM	http://www.itauc.com.br	
JITCO CO LTD	http://www.jitco.net/	Seong Jeon Tel: 82-32-817-9740 s.jeon@jitco.net
Kingston	http://www.kingston.com	US.- Call (877) 435-8726 Asia – Call 886-3-564-1539 Europe – Call +44-1932-755205
Legacy Electronics Inc.	http://www.legacyelectronics.com	U.S. Contact: Gary Ridenour, 949-498-9600, Ext 350 European Contact: 49 89 370 664 11
Legend	http://www.legend.com.au	
Micron	http://silicon.micron.com/mktg/http://silicon.micron.com/mktg/mbqual/qual_data.cfm	
MSC Vertriebs GmbH	http://www.msc-ge.com	William Perrigo 49-7249-910-417 Fax: 49-7249-910-229 wpe@msc-ge.com
Nanya Technology	http://www.ntc.com.tw	Winson Shao 886-3-328-1688, Ext 6018 winsonshao@ntc.com.tw

Vendor Name	Web URL	Vendor Direct Sales Info
Netlist, Inc	http://www.netlistinc.com	Christopher Lopes 949.435.0025 tel 949.435.0031 fax sales@netlistinc.com
Peripheral Enhancements	http://www.peripheral.com/	
Samsung	http://www.korea.samsungsemi.com/locate/buy/list_na.html	For US customers go to: http://www.mymemorystore.com/
Silicon Tech	http://www.silicontech.com/contact/salescontacts.shtml	
Simple Tech	http://www.simpletech.com	Ron Darwish @ (949) 260-8230 or email @ Rdarwish@Simpletech.com
SMART Modular Technologies	www.smartm.com/channel/hpc/	Gene Patino (949) 439-6167 Gene.Patino@Smartm.com
Swissbit	http://www.swissbit.com	Tony Cerreta Tel: 914-935-1400 x240 Fax: 914-935-9865 tony.cerreta@swissbitna.com
TechnoLinc Corporation	http://www.technolinc.com	David Curtis 510-445-7400 davidc@technolinc.com
TRS* Tele-Radio-Space GmbH	http://www.certified-memory.com http://www.certified-memory.de	Vendor Direct Sales Info: Andreas Gruendl Tel: +49.89.945532-34 Fax: +49.89.945532-41 Andreas.gruendl@trs-eu.com
Unigen	http://www.unigen.com	
Ventura Technology Inc	http://www.venturatech.com	Sam Lewis 760 724-8700 ext. 103
Viking InterWorks	http://www.vikinginterworks.com	Adrian Proctor Tel: 949-643-7255 adrian.proctor@sanmina-sci.com
Virtium Technology Inc	http://www.virtium.com	Tod Skelton @ (949) 460-0020 ext. 146 or email @ tod.skelton@virtium.com
Wintec Industries	http://www.wintecindustries.com	Tel 510-360-6300 Fax 510-770-9338

5. CMTL* (Computer Memory Test Labs)

CMTL is a privately owned and operated memory testing organization responsible for testing a broad range of memory products. Memory devices tested by CMTL must undergo a rigorous battery of tests to ensure that the product will perform the intended server functions. Memory capability is a major factor your customers consider. CMTL has the ability to test and certify memory on Intel-based server platforms. The list of memory modules, which have undergone testing through the CMTL facility, should be referenced when considering modules for integration into this Intel server product. Stringent standards with regard to manufacturing procedures and quality must be met to pass the exacting tests required for qualification through the independent testing facility. Testing is performed by CMTL with Intel server products and test procedures defined by Intel's Memory Qualification Lab. Intel routinely audits the CMTL facility to ensure all procedures, process handling, and testing methodologies are met.

IMPORTANT NOTE

DIMM devices with gold contacts should NOT be placed into DIMM sockets with tin-lead contacts or vice-versa. Mixing dissimilar metal contact types has been shown to result in unreliable memory operation. Intel recommends similar manufacturer and similar speeds in each Rank on the memory module. Mixing of dissimilar memory manufacturer devices or dissimilar memory device speeds is not recommended. This document contains information which is the proprietary property of Intel Corporation. Nothing in this document constitutes a guaranty, warranty, or license, express or implied. Intel has tested the following DIMMs for minimum electrical and functional compatibility with the Intel® Server RAID Controller. This listing is not intended to be all inclusive; it only represents the DIMMs Intel or CMTL has tested. Users of this list are reminded to check with the DIMM manufacturer or Distributor to ensure that a particular DIMM model is adequate for the intended purpose on the Intel® Server RAID Controller. Intel provides no indemnities for and expressly disclaims all liabilities for any and all such guaranties, representations, and warranties (oral or written) whether express or implied, related to DIMMs in a Intel® Server RAID Controller product, including without limitation to: fitness for a particular purpose; merchantability; noninfringement of intellectual property or other rights of any third party or of Intel. The reader is advised that third parties may have intellectual property rights which may be relevant to this document and the technologies discussed herein, and is advised to seek the advice of competent legal counsel, without obligation of Intel. Intel retains the right to make changes to this document at any time, without notice. Intel makes no warranty or representation with respect to the use of this document or reliance by the reader upon its contents, and assumes no responsibility for any errors which may appear in the document nor does it make a commitment to update the information contained herein.

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